

Dell PowerEdge R960

Technical Guide

Notes, cautions, and warnings

 **NOTE:** A NOTE indicates important information that helps you make better use of your product.

 **CAUTION:** A CAUTION indicates either potential damage to hardware or loss of data and tells you how to avoid the problem.

 **WARNING:** A WARNING indicates a potential for property damage, personal injury, or death.

Chapter 1: System overview.....	5
Key workloads.....	5
New technologies.....	6
Chapter 2: System features and generational comparison.....	7
Chapter 3: Chassis views and features.....	10
Front view of the system.....	10
Rear view of the system.....	12
Inside the system.....	13
Chapter 4: Processor.....	15
Processor features	15
Supported processors.....	15
Chapter 5: Memory subsystem.....	16
Supported memory.....	16
Chapter 6: Storage.....	17
Storage controllers.....	17
Supported Drives.....	17
Internal storage configuration.....	18
External Storage.....	18
Chapter 7: Networking.....	19
Overview.....	19
OCP 3.0 support.....	19
Supported OCP cards.....	19
OCP NIC 3.0 vs. rack Network Daughter Card comparisons.....	20
Chapter 8: PCIe subsystem.....	21
PCIe risers.....	21
Chapter 9: Power, thermal, and acoustics.....	30
Power.....	30
Power Supply Units.....	31
Thermal.....	32
Thermal design.....	32
Acoustics.....	33
Acoustical configurations of R960	33
Chapter 10: Rack, rails, and cable management.....	36
Rails and cable management information.....	36

Chapter 11: Operating Systems and Virtualization.....	44
Supported Operating Systems.....	44
Chapter 12: Dell OpenManage Systems Management.....	45
Integrated Dell Remote Access Controller (iDRAC).....	45
Systems Management software support matrix.....	46
Chapter 13: Appendix A: Additional specifications.....	48
Chassis dimension.....	48
Chassis weight.....	49
NIC port specifications.....	49
Video specifications.....	49
USB Ports.....	50
PSU rating.....	51
Environmental specifications.....	52
Thermal restriction matrix.....	54
Thermal air restrictions.....	58
Chapter 14: Appendix B. Standards compliance.....	59
Chapter 15: Appendix C Additional resources.....	60
Chapter 16: Appendix D: Services.....	61
Default service levels.....	61
ProDeploy Infrastructure Suite.....	61
Supplemental Deployment Services.....	64
Unique Deployment Scenarios.....	65
DAY 2 - Automation Services with Ansible.....	66
ProSupport Infrastructure Suite.....	66
Specialty Support Services.....	68
Dell Technologies Consulting Services.....	69
Resources.....	70

System overview

The Dell PowerEdge R960 is Dell's latest four-socket, rack server that is designed to run complex workloads using highly scalable memory, I/O, and network options.

The system features:

- Up to 4 x 4th Gen Intel® Xeon® Scalable Processors with up to 60 cores
- 64 DDR5 DIMM slots, supports maximum 16 TB
- Four AC or DC power supply units with 2+2 redundancy
- Up to 8 x 2.5-inch SAS/SATA (HDD/SSD) drives
- Up to 16 x 2.5-inch SAS/SATA (HDD/SSD) drives
- Up to 32 x 2.5-inch SAS/SATA (HDD/SSD) drives
- Up to 24 x 2.5-inch NVMe (SSD) drives
- Up to 16 x 2.5-inch SAS/SATA (HDD/SSD) + 8 x 2.5-inch NVMe (SSD) drives
- Up to 16 x EDSFF E3.S Gen5 NVMe (SSD) drives
- Up to 16 x EDSFF E3.S Gen5 NVMe (SSD) + 8 x 2.5-inch SAS/SATA (HDD/SSD) drives
- PCI Express® (PCIe) 5.0 enabled expansion slots
- Network interface technologies to cover Network Interface Card (NIC)
- Optional Direct Liquid Cooling

NOTE: For more information about how to hot swap NVMe PCIe SSD U.2 device, see the *Dell Express Flash NVMe PCIe SSD User's Guide* at [Dell Support > Browse all products > Infrastructure > Data Center Infrastructure > Storage Adapters & Controllers > Dell PowerEdge Express Flash NVMe PCIe SSD > Select This Product > Documentation > Manuals and Documents](#).

NOTE: All instances of SAS, SATA, NVMe drives are referred to as drives in this document, unless specified otherwise.

CAUTION: Do not install GPUs, network cards, or other PCIe devices on your system that are not validated and tested by Dell. Damage caused by unauthorized and invalidated hardware installation will null and void the system warranty.

Topics:

- [Key workloads](#)
- [New technologies](#)

Key workloads

Customers looking for accelerated compute to maximize performance in a dense, scalable server architecture to address the following applications:

- SAP/HANA, Oracle, SQL
- Database, ERP, CRM, batch
- Data warehouse, business intelligence
- Virtualization/VM and VDI
- AI, HPC and ML/DL

New technologies

Table 1. New technologies

Technology	Detailed Description
4 th Gen Intel® Xeon® Scalable Processors	Core count: Up to 60 core processor
	UPI speed: Up to 4 links per CPU, speed: 12.8 GT/s, 14.4 GT/s, 16 GT/s
	Maximum number of PCIe lanes per CPU: Integrated 80 PCIe 5.0 lanes @ 32GT/s PCIe Gen5
	Maximum TDP: 350 W
4800 MT/s DDR5 Memory	Max 16 DIMM per processor and 64 DIMMs per system
	Supports DDR5 ECC RDIMM
PCIe Gen	Gen5 @32 GT/s
PCIe Slot	Up to twelve Gen5 (x16) slots
Flex I/O	LOM board, 2x1Gb with BCM5720 LAN controller (optional)
	Rear I/O with: <ul style="list-style-type: none"> • 1x Dedicated iDRAC Ethernet port • 1 x USB 3.0 • 1 x USB 2.0 • 1 x VGA port
	Serial Port (Optional) with STD RIO board
	OCP Mezz 3.0 (supported by x16 PCIe lanes) (optional)
	Front I/O with: <ul style="list-style-type: none"> • 1 x USB 2.0 • 1x iDRAC Direct (Micro-AB USB) port • 1 x VGA port
CPLD 1-wire	Support payload data of Front PERC, Riser, BP and Rear IO to BOSS-N1 and iDRAC
Dedicated PERC	PERC 11: <ul style="list-style-type: none"> • H755, H355, HBA355i
	PERC 12: <ul style="list-style-type: none"> • H965i, H965e
Software RAID	OS RAID / S160
Power Supplies	60 mm dimension is the new PSU form factor on 15G design
	Titanium 1100 W AC/HVDC
	Platinum 1400 W AC/HVDC
	Titanium 1800 W AC/HVDC
	1100W DC
	86 mm dimension PSU
	Platinum 2400 W AC/HVDC
	Titanium 2800 W AC/HVDC

System features and generational comparison

The following table shows the comparison between the PowerEdge R960 with the PowerEdge R940xa.

Table 2. Features comparison

Features	PowerEdge R960	PowerEdge R940xa
Processors	4 x 4 th Gen Intel® Xeon® Scalable Processors	4 x 2 nd Generation Intel® Xeon® Scalable Processor
CPU interconnect	Intel Ultra Path Interconnect (UPI)	Intel Ultra Path Interconnect (UPI)
Memory	<ul style="list-style-type: none"> 64 x DDR5 RDIMM Up to 4800 MT/s (1 DPC) / 4400 MT/s (2 DPC) 	<ul style="list-style-type: none"> 48 x DDR4 RDIMM, LRDIMM 24 x PMem (Intel Optane Persistent Memory) 12 x NVDIMM
Storage Controllers	<ul style="list-style-type: none"> PERC 11G: H755, H355 PERC 12G: H965i, H965e HBA 11: HBA355i, HBA355e HBA 12: HBA465i, HBA465e BOSS-N1 Software RAID: S160 	<ul style="list-style-type: none"> PERC 9G: H330, H730p PERC 10G: H740p, H840 HBA 9: HBA330, 12 Gbps SAS HBA HBA 11: HBA355e BOSS adapter Software RAID: S140 Internal Dual SD Module
Drive Bays	Front bays: <ul style="list-style-type: none"> 2.5 inches - 24 Gb SAS, 6 Gb SATA, Gen3/4 NVMe E3.S - NVMe Gen5 EDSFF 	Front bays: <ul style="list-style-type: none"> 2.5 inches - 12 Gb SAS, 6 Gb SATA, Gen3 NVMe
Power Supplies	<ul style="list-style-type: none"> AC (Platinum): 1400 W, 2400 W AC (Titanium): 1100 W, 1800 W, 2800 W 1100 W DC 	<ul style="list-style-type: none"> AC (Platinum): 750 W, 1100 W, 1600 W, 2000 W, 2400 W AC (Titanium): 1600 W, 2600 W LVDC @ -48 VDC Input: 1100 W
Cooling Options	<ul style="list-style-type: none"> Air Cooling Optional Direct Liquid Cooling (DLC) <p>NOTE: DLC is a rack solution and requires rack manifolds and a cooling distribution unit (CDU) to operate.</p>	<ul style="list-style-type: none"> Air Cooling
Fans	Standard (STD) fans	Standard (STD) fans
	Up to six sets (dual fan module) hot plug fans	Up to six hot swap fans
Dimension	Height: 174.3 mm (6.86 inches)	Height: 174.3 mm (6.86 inches)
	Width: 482 mm (18.97 inches)	Width: 441.16 mm (17.37 inches)
	Depth: 883.195 mm (34.77 inches) with bezel	Depth: 877.84 mm (34.56 inches) with bezel
	869.195 mm (34.22 inches) without bezel	865.9 (34.09 inches) without bezel
Form Factor	4U rack server	4U rack server
Embedded Management	<ul style="list-style-type: none"> iDRAC9 iDRAC Direct iDRAC RESTful with Redfish 	<ul style="list-style-type: none"> iDRAC9 iDRAC Direct Quick Sync 2 BLE/wireless module

Table 2. Features comparison (continued)


Features	PowerEdge R960		PowerEdge R940xa	
	<ul style="list-style-type: none"> • iDRAC Service Manual • Quick Sync 2 wireless module 			
Bezel	Optional LCD bezel or security bezel		Optional LCD bezel or security bezel	
OpenManage Software	<ul style="list-style-type: none"> • CloudIQ for PowerEdge plug in • OpenManage Enterprise • OpenManage Enterprise Integration for VMware vCenter • OpenManage Integration for Microsoft System Center • OpenManage Integration with Windows Admin Center • OpenManage Power Manager plugin • OpenManage Service plugin • OpenManage Update Manager plugin 		<ul style="list-style-type: none"> • OpenManage Enterprise • OpenManage Power Center 	
Mobility	OpenManage Mobile		OpenManage Mobile	
Integrations and Connections	OpenManage Integrations <ul style="list-style-type: none"> • BMC TrueSight • Microsoft System Center • OpenManage Integration with ServiceNow • Red Hat Ansible Modules • Terraform Providers • VMware vCenter and vRealize Operations Manager 		OpenManage Integrations <ul style="list-style-type: none"> • BMC TrueSight • Microsoft System Center • Red Hat Ansible Modules • VMware vCenter 	<ul style="list-style-type: none"> • IBM Tivoli Netcool/OMNIBus • Micro Focus Operations Manager I • Nagios Core • Nagios XI
Security	<ul style="list-style-type: none"> • Cryptographically signed firmware • Secure Boot • Secure Erase • Silicon Root of Trust • System Lockdown (requires iDRAC9 Enterprise or Datacenter) • TPM 2.0 FIPS, CC-TCG certified, TPM 2.0 China NationZ • Secured Component Verification (Hardware integrity check) • Data at Rest Encryption (SEDs with local or external key mgmt) 		<ul style="list-style-type: none"> • Cryptographically signed firmware • Secure Boot • Secure Erase • Silicon Root of Trust • System Lockdown (requires iDRAC9 Enterprise or Datacenter) • TPM 1.2/2.0 FIPS, CC-TCG certified, TPM 2.0 China NationZ 	
Embedded NIC	2 x 1 GbE LOM (optional)		4 x 1 GbE Network Daughter Card (optional)	
Networking Options	OCP x16 (optional) Mezz 3.0  NOTE: The system allows either LOM card or an OCP card or both to be installed in the system.		NA	
GPU Options	Up to four double wide 400 W		Up to two double wide 300 W, or eight single wide 75 W accelerators	
Ports	Front Ports <ul style="list-style-type: none"> • 1 x USB 2.0 • 1 x VGA • 1 x iDRAC Direct (Micro-AB USB) port 	Rear Ports <ul style="list-style-type: none"> • 1 x USB 2.0 • 1 x Dedicated iDRAC Ethernet port • 1 x USB 3.0 • 1 x Serial port (optional) • 1 x VGA 	Front Ports <ul style="list-style-type: none"> • 1 x Dedicated iDRAC micro-USB • 2 x USB 2.0 • 1 x VGA 	Rear Ports <ul style="list-style-type: none"> • 2 x USB 3.0 • 1 x Dedicated iDRAC Ethernet port • 1 x Serial port • 1 x VGA

Table 2. Features comparison (continued)

Features	PowerEdge R960	PowerEdge R940xa
	Internal Port: 1 x USB 3.0 (optional)	Internal Port: 1 x USB 3.0 (optional)
PCIe	Up to 12 x PCIe Gen5 slots	Up to 12 x Gen3 slots (6x16 slots or 2x16 + 10x8 slots)
Operating System and Hypervisors	<ul style="list-style-type: none"> • Canonical Ubuntu Server LTS • Microsoft Windows Server with Hyper-V • Red Hat Enterprise Linux • SUSE Linux Enterprise Server • VMware ESXi <p>For specifications and interoperability details, see Dell Enterprise Operating Systems on Servers, Storage, and Networking page at Dell.com/OSsupport.</p>	<ul style="list-style-type: none"> • Canonical Ubuntu Server LTS • Citrix Hypervisor • Windows Server LTSC with Hyper-V • Red Hat Enterprise Linux • SUSE Linux Enterprise Server • VMware ESXi <p>For specifications and interoperability details, see Dell Enterprise Operating Systems on Servers, Storage, and Networking page at Dell.com/OSsupport.</p>

Chassis views and features

Topics:

- Front view of the system
- Rear view of the system
- Inside the system

Front view of the system



Figure 1. Front view of 32 x 2.5-inch drive system (Smart Flow)

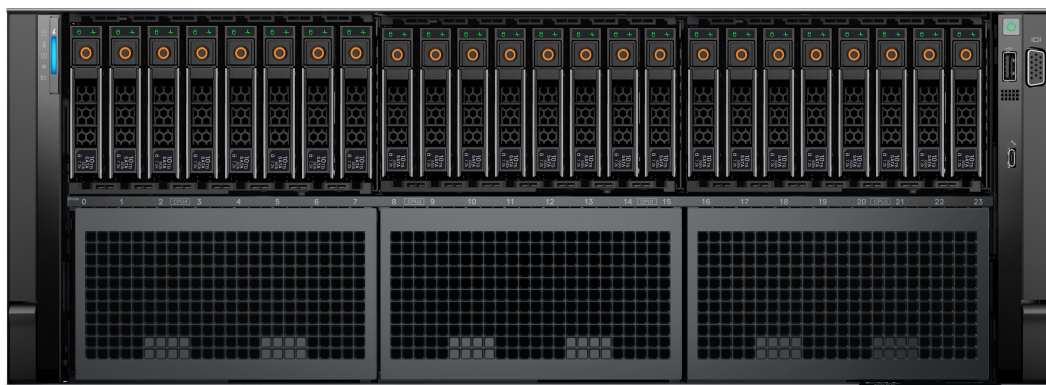


Figure 2. Front view of 24 x 2.5-inch drive system

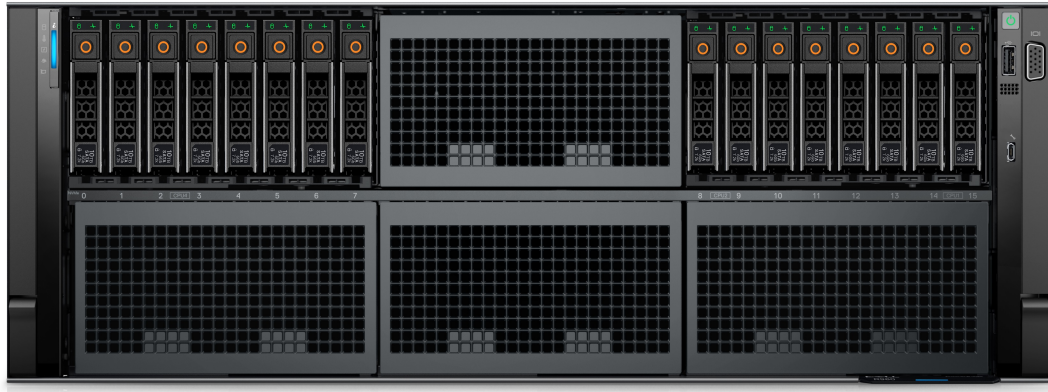


Figure 3. Front view of 16 x 2.5-inch drive system

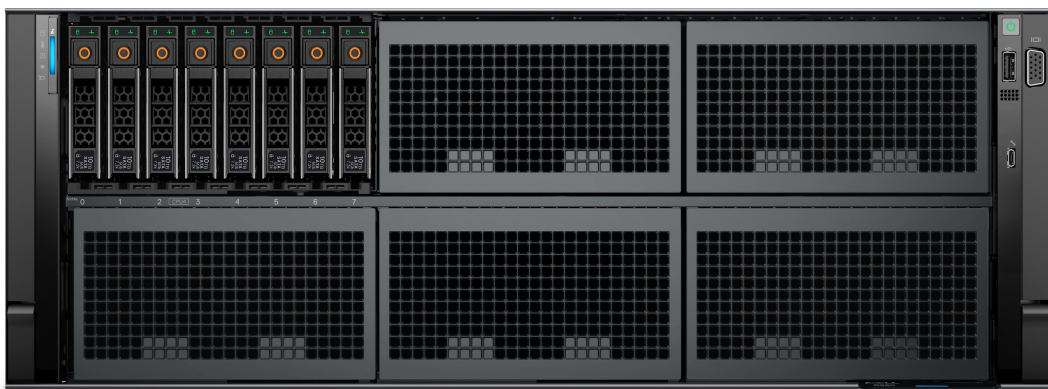


Figure 4. Front view of 8 x 2.5-inch drive system

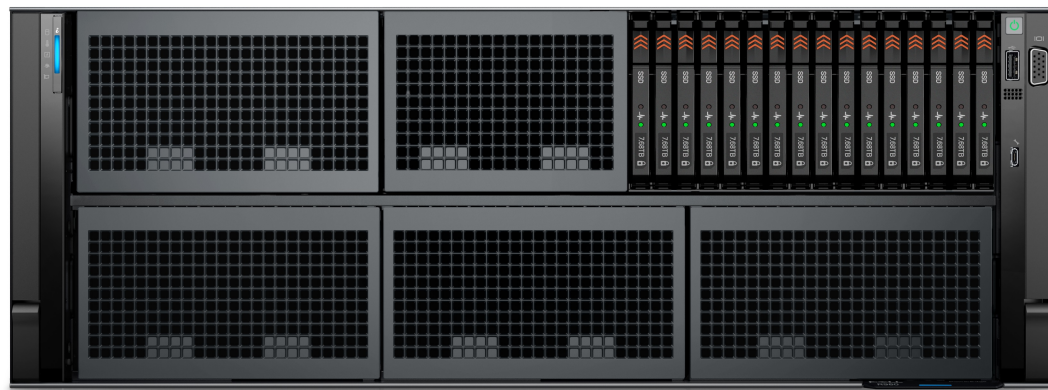


Figure 5. Front view of 16 x EDSFF E3.S Gen5 NVMe drive system

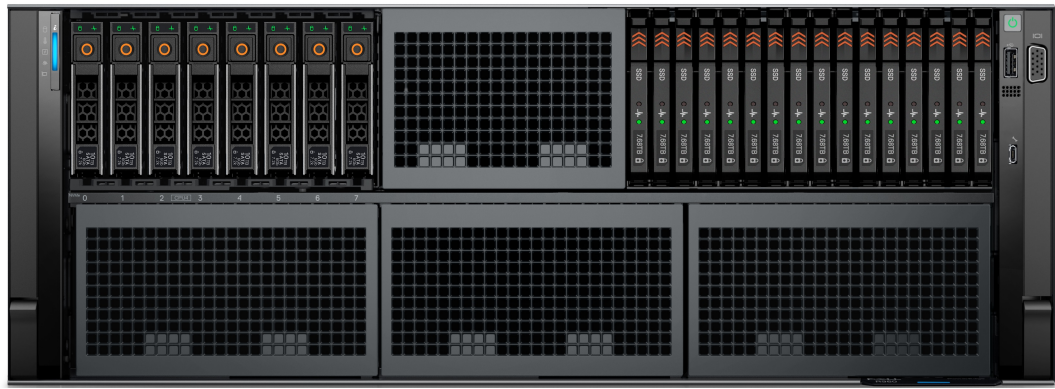


Figure 6. Front view of 16 x EDSFF E3.S Gen5 NVMe with 8 x 2.5-inch drive system

Rear view of the system

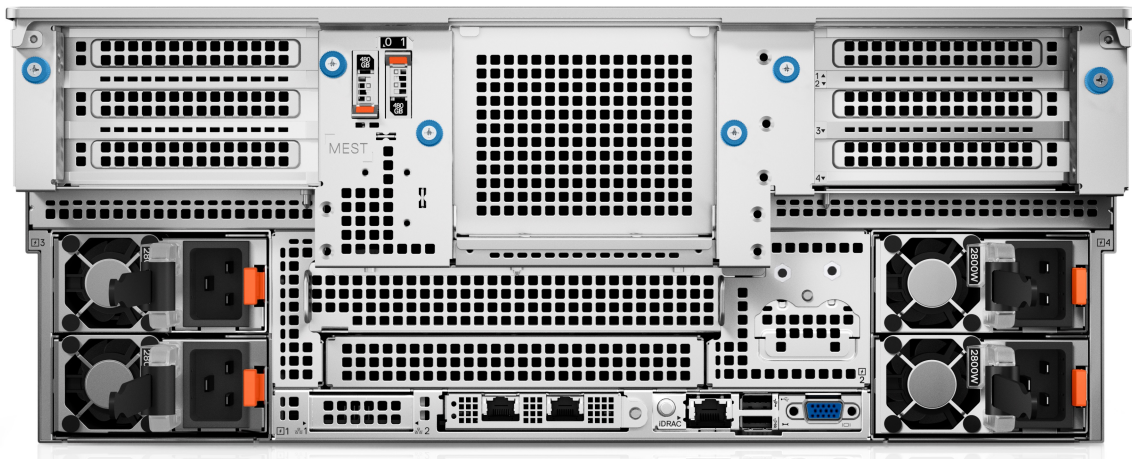


Figure 7. Rear view of the system with basic configuration

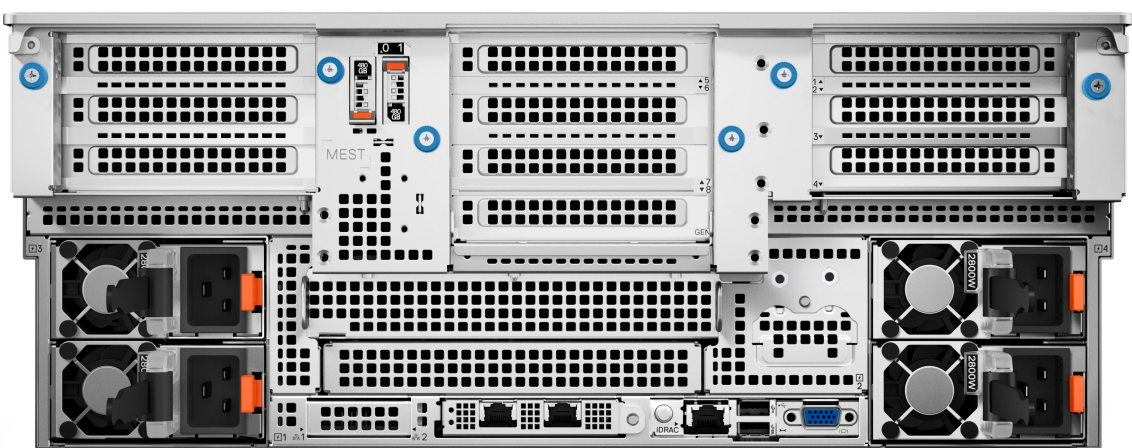


Figure 8. Rear view of the system with scale out configuration

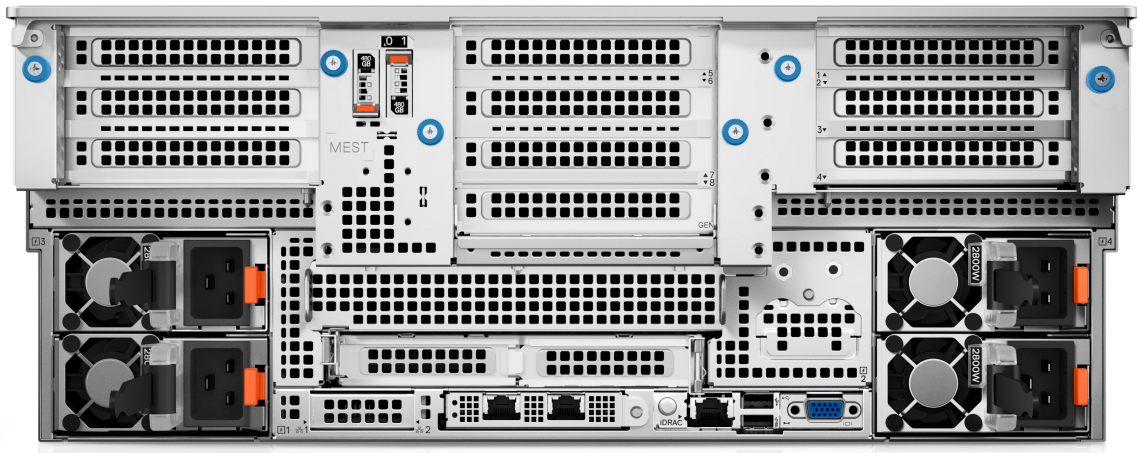


Figure 9. Rear view of the system with maximum I/O configuration

Inside the system



Figure 10. Inside the system

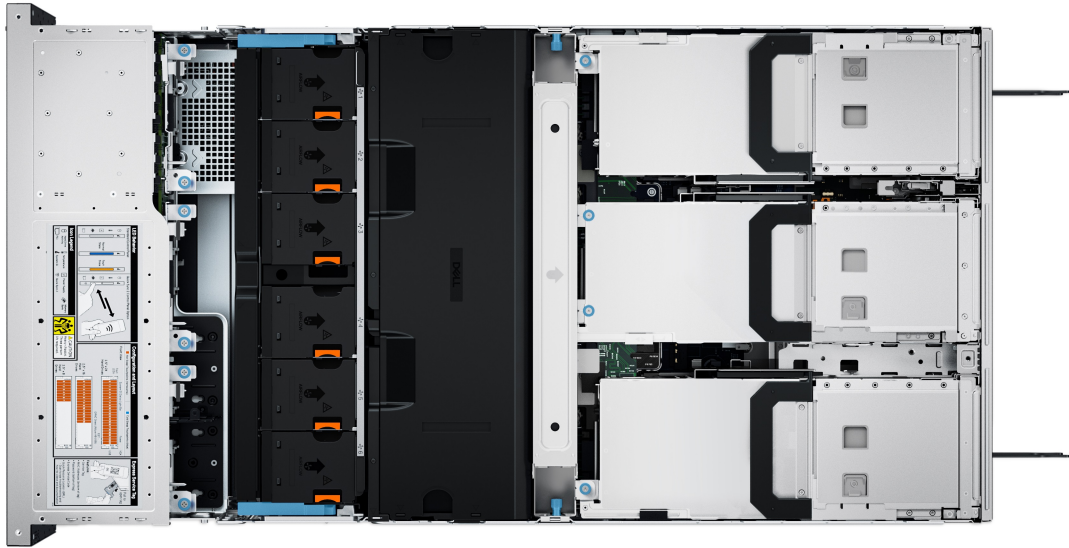


Figure 11. Inside the system with full length risers and GPU shroud

Processor

Topics:

- [Processor features](#)

Processor features

The 4th Generation Intel® Xeon® Processors stack is the next generation data center processor offering with significant performance increases, integrated acceleration, and next generation memory and I/O. Sapphire Rapids accelerate customer usages with unique workload optimizations.

The following lists the features and functions that are in the 4th Generation Intel® Xeon® Scalable Processor offering:

- Faster UPI with up to four Intel Ultra Path Interconnect (Intel UPI) at up to 16 GT/s, increasing multisocket bandwidth
- More, faster I/O with PCI Express 5 and up to 80 lanes (per socket)
- Enhanced Memory Performance with DDR5 support and memory speed up to 4800 MT/s in one DIMM per channel (1DPC) and 4400 MT/s in two DIMM per channel (2DPC)
- New built-in accelerators for data analytics, networking, storage, crypto, and data compression

Supported processors

The following table shows the Intel Sapphire Rapids SKUs that are supported on the R960.

Table 3. Supported processors for R960

Processor	Clock Speed (GHz)	Cache (M)	UPI (GT/s)	Cores	Threads	Turbo	Memory Speed (MT/s)	Memory Capacity	TDP
8490H ¹	1.9	113	16	60	120	Turbo	4800	4 TB	350 W
8468H ¹	2.1	105	16	48	96	Turbo	4800	4 TB	330 W
8460H ¹	2.2	105	16	40	80	Turbo	4800	4 TB	330 W
8454H ¹	2.1	83	16	32	64	Turbo	4800	4 TB	270 W
8450H ¹	2	75	16	28	56	Turbo	4800	4 TB	250 W
8444H ¹	2.9	45	16	16	32	Turbo	4800	4 TB	270 W
6448H	2.4	60	16	32	64	Turbo	4800	4 TB	250 W
6434H	3.7	23	16	8	16	Turbo	4800	4 TB	195 W
6418H	2.1	60	16	24	48	Turbo	4800	4 TB	185 W
6416H	2.2	45	16	18	36	Turbo	4800	4 TB	165 W

NOTE: Mixing of the processors in a 4S configurations is not recommended.

NOTE: ¹Only the processors that are listed above can support 96 GB RDIMM.

Memory subsystem

Topics:

- Supported memory

Supported memory

Table 4. Memory technology comparison

Feature	PowerEdge R960 (DDR5)
DIMM type	RDIMM
Transfer speed	4800 MT/s (1DPC), 4400 MT/s (2DPC)
Voltage	1.1 V

Table 5. Supported memory matrix

DIMM type	Rank	Capacity	DIMM rated voltage and speed	Operating Speed	
				1 DIMM per channel (DPC)	2 DIMMs per channel (DPC)
RDIMM	1 R	16 GB	DDR5 (1.1 V), 4800 MT/s or 5600 MT/s	4800 MT/s	4400 MT/s
	2 R	32 GB, 64 GB	DDR5 (1.1 V), 4800 MT/s or 5600 MT/s	4800 MT/s	4400 MT/s
	2 R	96 GB	DDR5 (1.1 V), 5600 MT/s	4800 MT/s	4400 MT/s
	2 R	128 GB	DDR5 (1.1 V), 5600 MT/s	4800 MT/s	4400 MT/s
	4 R	128 GB	DDR5 (1.1 V), 4800 MT/s	4800 MT/s	4400 MT/s
	8 R	256 GB	DDR5 (1.1 V), 4800 MT/s	4800 MT/s	4400 MT/s

NOTE: The processor may reduce the performance of the rated DIMM speed.

NOTE: Only 8 or 16 DIMMs per processor are compatible with 96 GB RDIMMs.

NOTE: Few processors that are listed in the [supported processors](#) section support 96 GB RDIMM.

Storage

Topics:

- [Storage controllers](#)
- [Supported Drives](#)
- [Internal storage configuration](#)
- [External Storage](#)

Storage controllers

Dell RAID controller options offer performance improvements, including the fPERC solution. fPERC provides a base RAID HW controller without consuming a PCIe slot by using a small form factor and high-density connector to the base planar.

16G PERC Controller offerings are a heavy leverage of the 15G PERC family. The Value and Value Performance levels carry over to 16G from 15G. New to 16G is the Avenger-based Premium Performance tier offering. This high-end offering drives IOPs performance and enhanced SSD performance.

Table 6. PERC Series controller offerings

Performance Level	Controller and Description
Entry	S160
Value	H355, HBA355 (internal/external), H465 (internal/external)
Value Performance	H755
Premium Performance	H965i, H965e

NOTE: PowerEdge does not support Tri-Mode, the mixing of SAS, SATA, and NVMe behind the same controller.

NOTE: For more information about the features of the Dell PowerEdge RAID controllers (PERC), Software RAID controllers, or BOSS card, and on deploying the cards, see the storage controller documentation at [Storage Controller Manuals](#).

NOTE: From December 2021, H355 replaces H345 as the entry raid controller. H345 is deprecated in January 2022.

Supported Drives

The table that is shown below lists the internal drives that are supported by the R960.

Table 7. Supported drives

Form Factor	Type	Speed	Rotational Speed	Capacities
2.5 inches	vSAS	12 Gb	SSD	1.92 TB, 3.84 TB, 960 GB, 7.62 TB
2.5 inches	SAS	24 Gb	SSD	1.92 TB, 1.6 TB, 800 GB, 3.84 TB, 960 GB, 7.68 TB
2.5 inches	SATA	6 Gb	SSD	1.92 TB, 480 GB, 960 GB, 3.84 TB
2.5 inches	NVMe	Gen4	SSD	1.6 TB, 3.2 TB, 6.4 TB, 1.92 TB, 3.84 TB, 15.63 TB, 7.68 TB, 800 GB, 400 GB


Table 7. Supported drives (continued)

Form Factor	Type	Speed	Rotational Speed	Capacities
2.5 inches	DC NVMe	Gen4	SSD	3.84 TB, 960 GB
2.5 inches	SAS	12 Gb	10 K	600 GB, 1.2 TB, 2.4 TB
EDSFF E3.S	NVMe	Gen5	SSD	3.84 TB, 7.68 TB

Internal storage configuration

R960 available internal storage configurations:

- 8 x 2.5" (SAS/SATA) - Smartflow
- 16 x 2.5" (SAS4/SATA) - Smartflow
- 16 x 2.5" (SAS4/SATA) + 8 x 2.5" NVMe
- 32 x 2.5" (SAS4/SATA) - Dual Controller
- 24 x 2.5" (NVMe Gen4) Passive
- 16 x EDSFF E3.S (NVMe Gen5)
- 16 x EDSFF E3.S (NVMe Gen5) + 8 x 2.5" (SAS4/SATA)

 **NOTE:** The Universal Backplane supports HW RAID for SAS/SATA with direct attach NVMe, and does not support HW RAID for NVMe.

External Storage

The R960 support the external storage device types listed in the table below.

Table 8. Support external storage devices

Device Type	Description
External Tape	Supports connection to external USB tape products
NAS/IDM appliance software	Supports NAS software stack
JBOD	Supports connection to 12 Gb MD-series JBODs

Networking

Topics:

- [Overview](#)
- [OCP 3.0 support](#)

Overview

PowerEdge offers a wide variety of options to get information moving to and from our servers. Industry best technologies are chosen, and systems management features are added by our partners to firmware to tie in with iDRAC. These adapters are rigorously validated for worry-free, fully supported use in Dell servers.

OCP 3.0 support

Table 9. OCP 3.0 feature list

Feature	OCP 3.0
Form factor	SFF
PCIe Gen	Gen4
Max PCIe width	x16
Max number of ports	4
Port type	BT/SFP/SFP+/SFP28/SFP56/QSFP56
Max port speed	100 GbE
NC-SI	Yes
SNAPI	Yes
WoL	Yes
Power consumption	15 W–35 W

Supported OCP cards

Table 10. Supported OCP cards

Form factor	Vendor	Port type	Port speed	Port count
OCP 3.0	Broadcom	SFP28	25 GbE	4
	Broadcom	SFP28	25 GbE	2
	Intel	SFP28	25 GbE	4
	Intel	SFP28	25 GbE	2
	Broadcom	BT	10 GbE	4
	Broadcom	SFP+	10 GbE	2

Table 10. Supported OCP cards (continued)

Form factor	Vendor	Port type	Port speed	Port count
	Broadcom	BT	1 GbE	4
	Intel	SFP+	1 GbE	4
	Broadcom	QSFP56	100 GbE	2
	Mellanox	QSFP56	100 GbE	2
	Mellanox	SFP28	25 GbE	2
	Intel	SFP+	1 GbE	4
	Intel	SFP+	10 GbE	4
	Intel	SFP+	10 GbE	2

OCP NIC 3.0 vs. rack Network Daughter Card comparisons

Table 11. OCP 3.0, 2.0, and rNDC NIC comparison

Form Factor	Dell rNDC	OCP 2.0 (LOM Mezz)	OCP 3.0	Notes
PCIe Gen	Gen 3	Gen 3	Gen 4	Supported OCP3 is SFF (small form factor).
Max PCIe Lanes	x8	Up to x16	Up to x16	See server slot priority matrix.
Shared LOM	Yes	Yes	Yes	This is iDRAC port redirect.
Aux Power	Yes	Yes	Yes	Used for Shared LOM

PCIe subsystem

Topics:

- [PCIe risers](#)

PCIe risers

Shown below are the riser offerings for the platform.

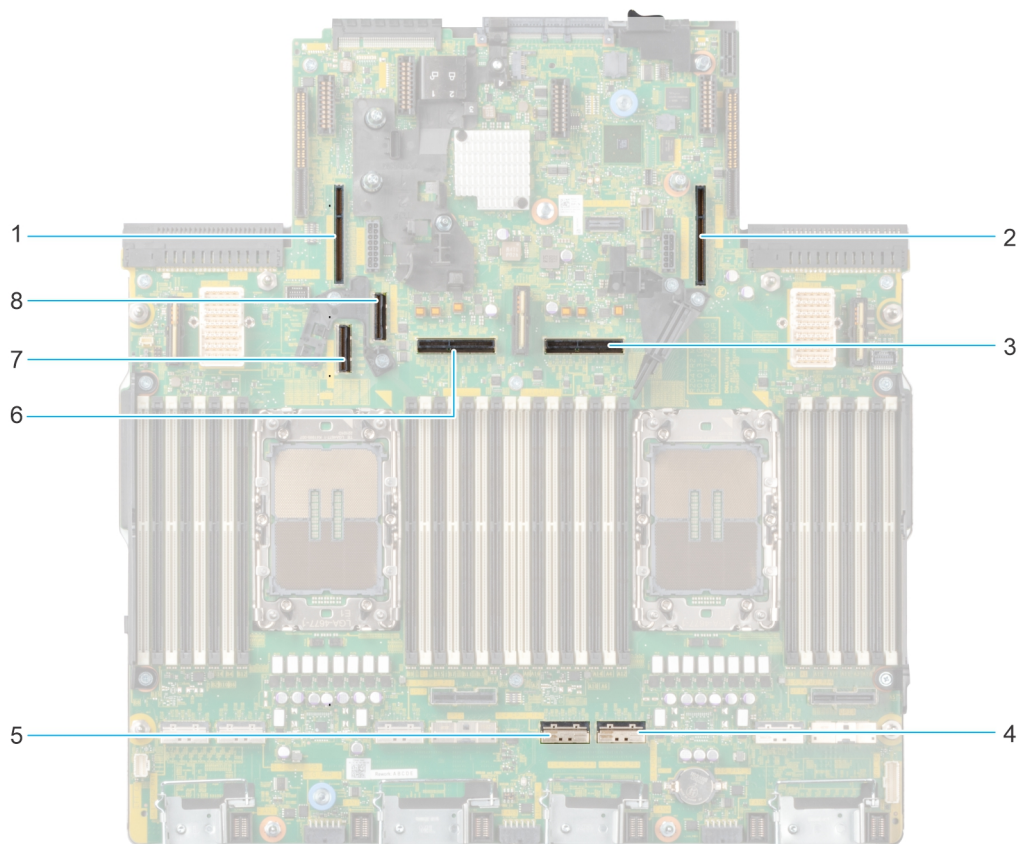


Figure 12. Riser connector location on system board

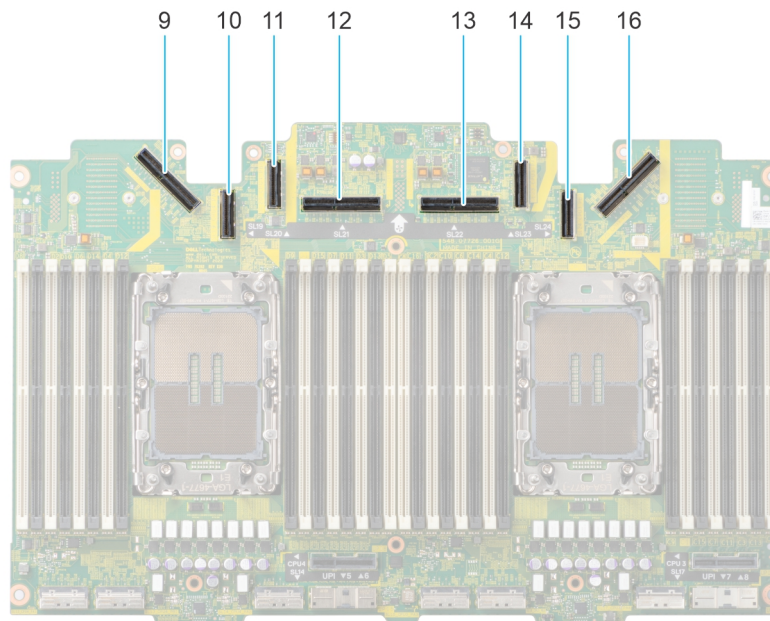


Figure 13. Riser connector location on PEM board

- | | |
|---|------------------------|
| 1. Riser 4A/4B/4C slot | 2. Riser 1A/1B/1C slot |
| 3. Riser 2 cable slot / Riser 3B cable slot | 4. Riser 1B cable slot |

NOTE: If present, riser 2 uses the connector, otherwise riser 3B uses it.

- | | |
|------------------------|---|
| 5. Riser 1B cable slot | 6. Riser 2 cable slot / Riser 3B cable slot |
|------------------------|---|

NOTE: If present, riser 2 uses the connector, otherwise riser 3B uses it.

- | | |
|------------------------------|----------------------------|
| 7. Riser 4B cable slot | 8. Riser 4B cable slot |
| 9. Riser 4A/4B/4C cable slot | 10. Riser 3B cable slot |
| 11. Riser 3B cable slot | 12. Riser 3A/3B cable slot |

NOTE: If riser 2 is present, riser 3A/3B uses this connector.

- | | |
|----------------------------|-------------------------|
| 13. Riser 3A/3B cable slot | 14. Riser 3B cable slot |
|----------------------------|-------------------------|

NOTE: If riser 2 is present, riser 3A/3B uses this connector.

- | | |
|-------------------------|-------------------------------|
| 15. Riser 3B cable slot | 16. Riser 1A/1B/1C cable slot |
|-------------------------|-------------------------------|

NOTE: A riser can be connected to the riser slot or riser cable slot or both depending on the type of riser used.

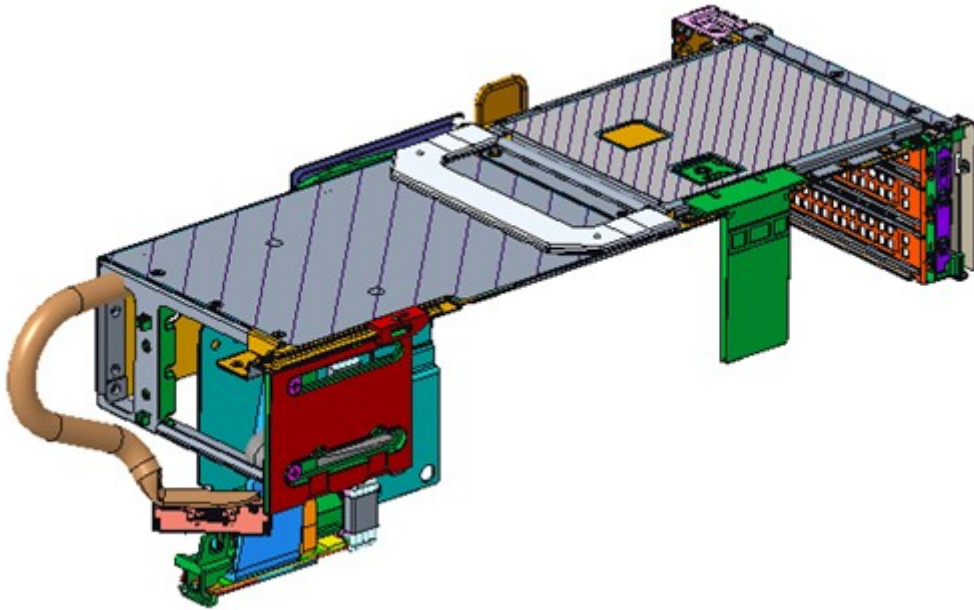


Figure 14. Riser 1A (FL)

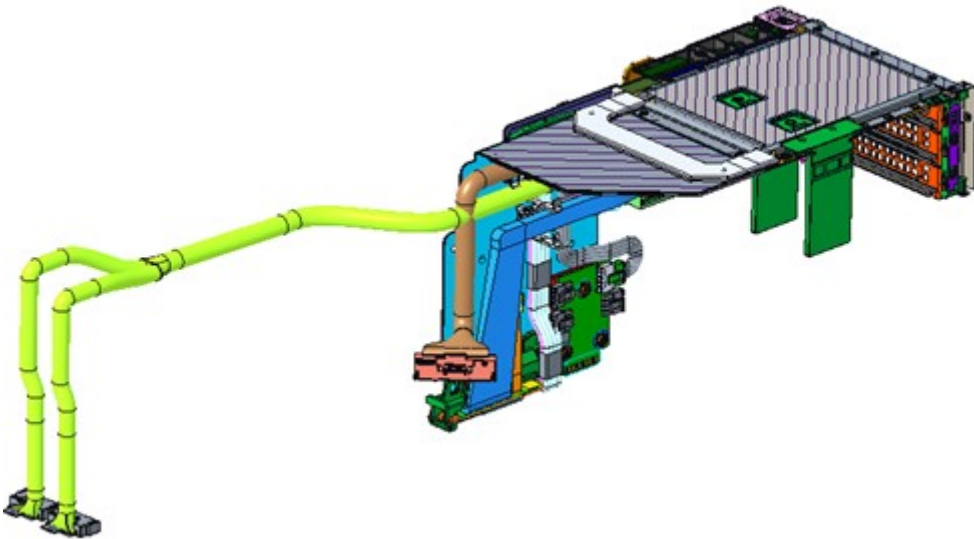


Figure 15. Riser 1B

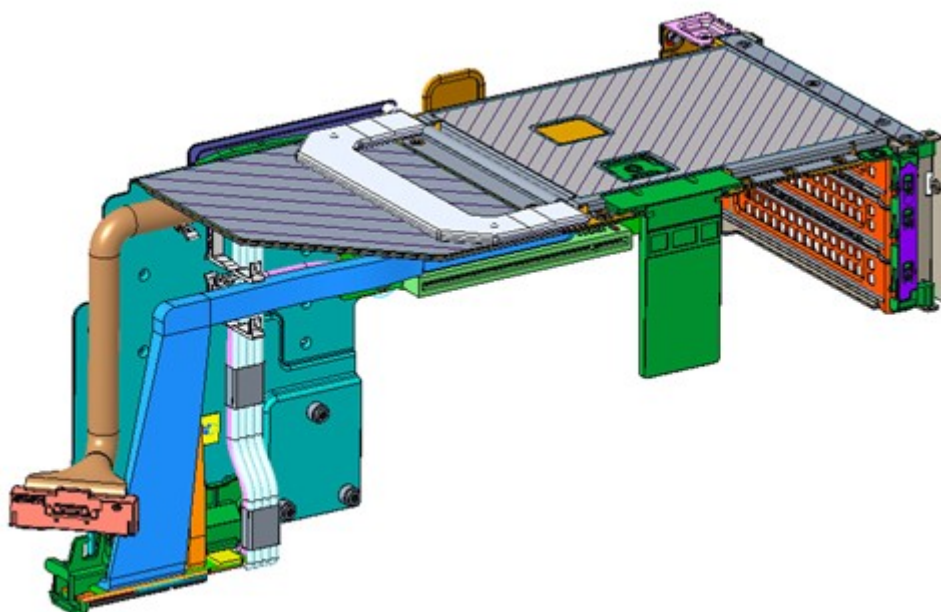


Figure 16. Riser 1C

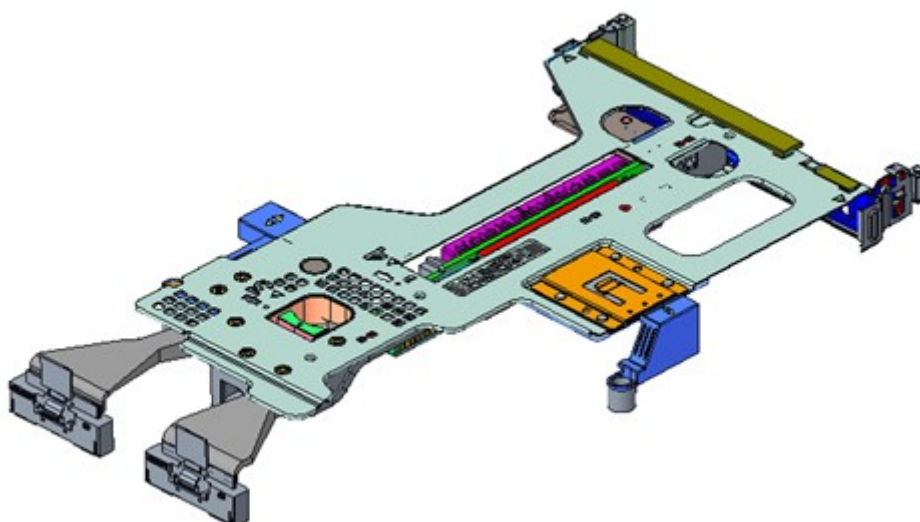


Figure 17. Riser 2

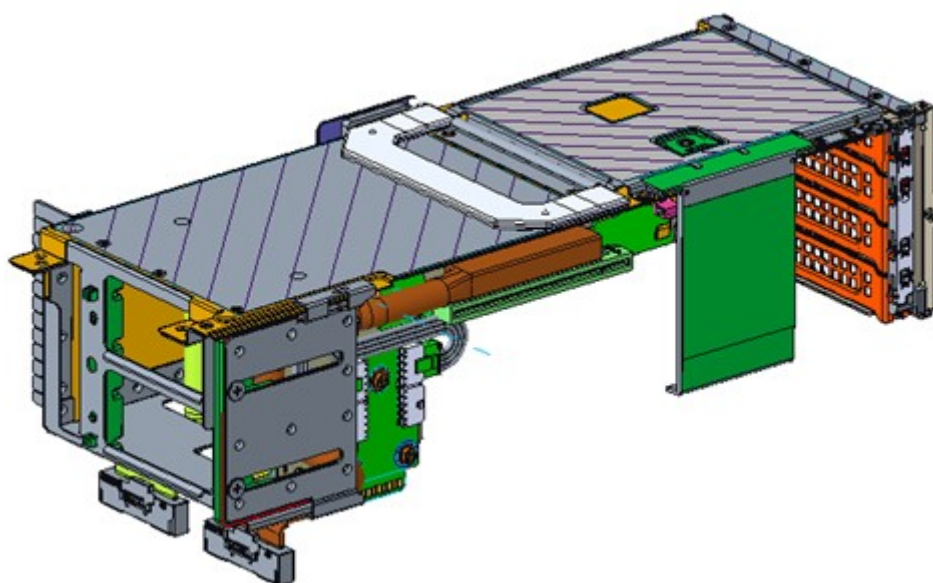


Figure 18. Riser 3A (FL)

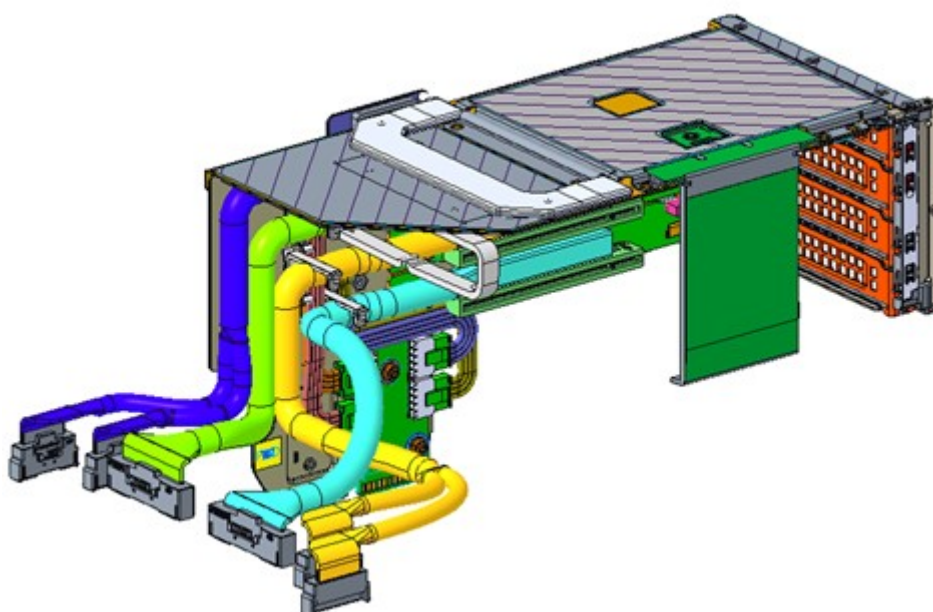


Figure 19. Riser 3B

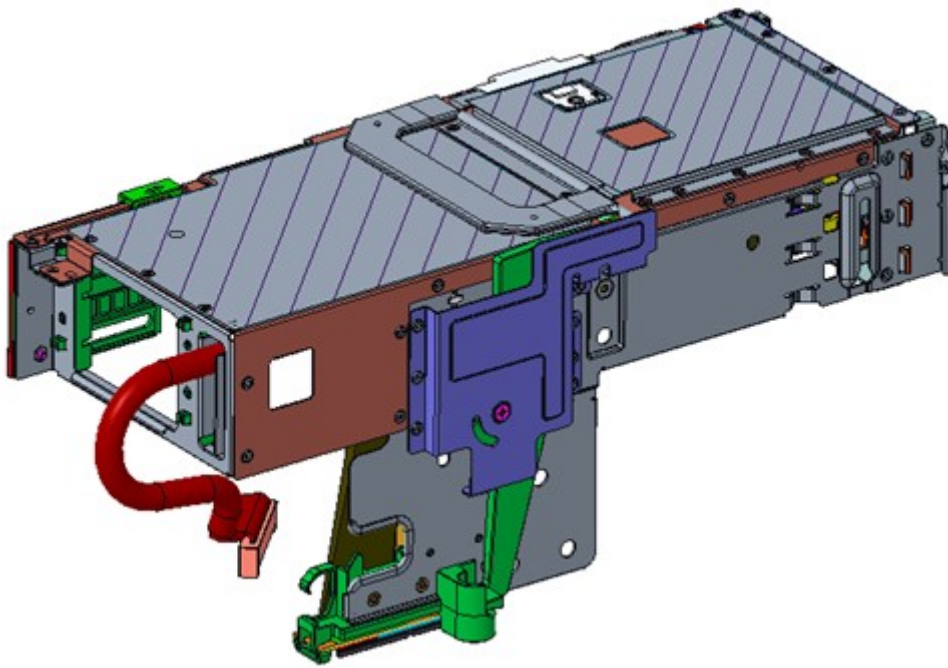


Figure 20. Riser 4A (FL)

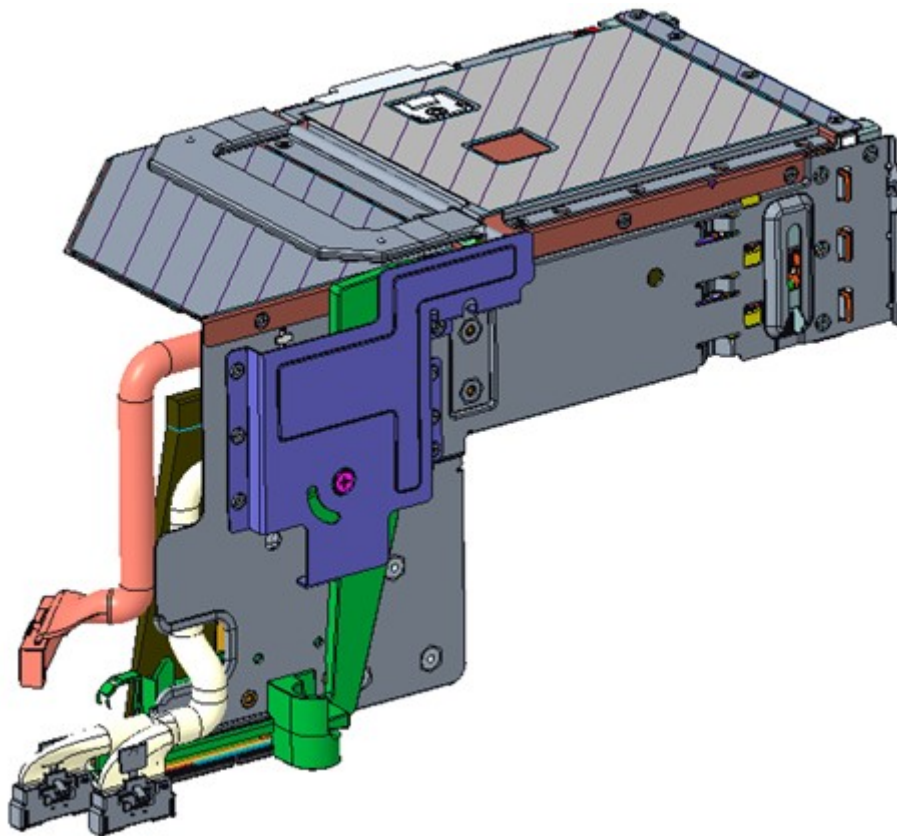


Figure 21. Riser 4B

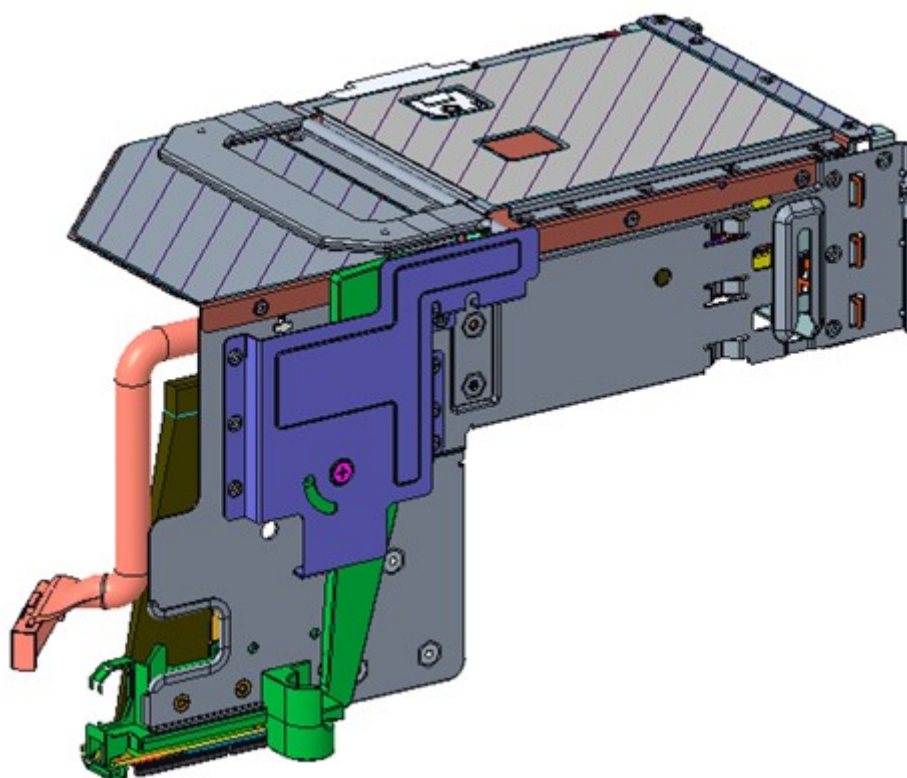


Figure 22. Riser 4C

Table 12. PCIe Riser Configurations

Config No.	Riser configuration	No. of Processors	PERC type supported	Rear storage possible
0-1 (Basic entry)	R1C+R4C	4	Front PERC	No
0-2 (Basic entry)	R1C+R4C	2	Front PERC	No
1 (Scale out)	R1C+R3B+R4C	4	Front PERC	No
2 (Maximum I/O)	R1B+R2+R3B+R4B	4	Front PERC	No
3 (GPU)	R1A+R2+R3A+R4A (FL)	4	Front PERC	No

Table 13. Riser Config 0-1: R1C+R4C

Supporting Processor				CPU3	CPU1	CPU4	CPU2
Location	Width	Length	Height	R1C		R4C	
PCIe Slot-1	SW	HL	FH	Gen5 x16	-	-	-
PCIe Slot-3	SW	HL	FH	-	Gen5 x16	-	-
PCIe Slot-10	SW	HL	FH	-	-	Gen5 x16	-
PCIe Slot-11	SW	HL	FH	-	-	-	Gen5 x16

Table 14. Riser Config 0-2: R1C+R4C

Supporting Processor				CPU3	CPU1	CPU4	CPU2
Location	Width	Length	Height	R1C		R4C	
PCIe Slot-1	SW	HL	FH	N/A	-	-	-
PCIe Slot-3	SW	HL	FH	-	Gen5 x16	-	-
PCIe Slot-10	SW	HL	FH	-	-	N/A	-

Table 14. Riser Config 0-2: R1C+R4C (continued)

Supporting Processor				CPU3	CPU1	CPU4	CPU2
Location	Width	Length	Height	R1C		R4C	
PCIe Slot-11	SW	HL	FH	-	-	-	Gen5 x16

Table 15. Riser Config 1: R1C+R3B+R4C

Supporting Processor				CPU3	CPU1	CPU4	CPU2	CPU3	CPU1	CPU4	CPU2
Location	Width	Length	Height	R1C		R3B				R4C	
PCIe Slot-1	SW	HL	FH	Gen5 x16	-	-	-	-	-	-	-
PCIe Slot-3	SW	HL	FH	-	Gen5 x16	-	-	-	-	-	-
PCIe Slot-5	SW	HL	FH	-	-	Gen5 x16	-	-	-	-	-
PCIe Slot-6	SW	HL	FH	-	-	-	Gen5 x16	-	-	-	-
PCIe Slot-7	SW	HL	FH	-	-	-	-	Gen5 x16	-	-	-
PCIe Slot-8	SW	HL	FH	-	-	-	-	-	Gen5 x16	-	-
PCIe Slot-10	SW	HL	FH	-	-	-	-	-	-	Gen5 x16	-
PCIe Slot-11	SW	HL	FH	-	-	-	-	-	-	-	Gen5 x16

Table 16. Riser Config 2: R1B+R2+R3B+R4B

Supporting Processor				CPU1	CPU3	CPU1	CPU2	CPU3	CPU4	CPU2	
Location	Width	Length	Height	R1B		R2		R3B		R4B	
PCIe Slot-1	SW	HL	FH	-	Gen5 x16	-	-	-	-	-	-
PCIe Slot-2	SW	HL	FH	Gen5 x16	-	-	-	-	-	-	-
PCIe Slot-3	SW	HL	FH	Gen5 x16	-	-	-	-	-	-	-
PCIe Slot-4	SW	HL	LP	-	-	-	Gen5 x16	-	-	-	-
PCIe Slot-5	SW	HL	FH	-	-	-	-	-	Gen5 x16	-	-
PCIe Slot-6	SW	HL	FH	-	-	-	-	-	Gen5 x16	-	-
PCIe Slot-7	SW	HL	FH	-	-	-	-	Gen5 x16	-	-	-
PCIe Slot-8	SW	HL	FH	-	-	-	-	Gen5 x16	-	-	-
PCIe Slot-9	SW	HL	LP	-	-	Gen5 x16	-	-	-	-	-
PCIe Slot-10	SW	HL	FH	-	-	-	-	-	-	Gen5 x16	-
PCIe Slot-11	SW	HL	FH	-	-	-	-	-	-	-	Gen5 x16
PCIe Slot-12	SW	HL	FH	-	-	-	-	-	-	-	Gen5 x16

Table 17. Riser Config 3: R1A+R2+R3A+R4A

Supporting Processor				CPU1	CPU3	CPU1	CPU2	CPU3	CPU4	CPU2	
Location	Width	Length	Height	R1A		R2		R3A		R4A	
PCIe Slot-1	SW	FL	FH	-	Gen5 x16	-	-	-	-	-	-
PCIe Slot-3	DW	FL	FH	Gen5 x16	-	-	-	-	-	-	-
PCIe Slot-4	SW	HL	LP	-	-	-	Gen5 x16	-	-	-	-
PCIe Slot-6	DW	FL	FH	-	-	-	-	-	Gen5 x16	-	-
PCIe Slot-8	DW	FL	FH	-	-	-	-	Gen5 x16	-	-	-
PCIe Slot-9	SW	HL	LP	-	-	Gen5 x16	-	-	-	-	-
PCIe Slot-10	SW	FL	FH	-	-	-	-	-	-	Gen5 x16	-
PCIe Slot-11	DW	FL	FH	-	-	-	-	-	-	-	Gen5 x16

Power, thermal, and acoustics

PowerEdge servers have an extensive collection of sensors that automatically track thermal activity, which helps to regulate temperature by reducing server noise and power consumption. The table below lists the tools and technologies Dell offers to lower power consumption and increase energy efficiency.

Topics:

- [Power](#)
- [Thermal](#)
- [Acoustics](#)

Power

Table 18. Power tools and technologies

Feature	Description
Power Supply Units(PSU) portfolio	Dell's PSU portfolio includes intelligent features such as dynamically optimizing efficiency while maintaining availability and redundancy. Find additional information in the Power supply units section.
Tools for right sizing	Enterprise Infrastructure Planning Tool (EIPT) is a tool that can help you determine the most efficient configuration possible. With Dell's EIPT, you can calculate the power consumption of your hardware, power infrastructure, and storage at a given workload. Learn more at Dell EIPT .
Industry Compliance	Dell's servers are compliant with all relevant industry certifications and guide lines, including 80 PLUS, Climate Savers and ENERGY STAR.
Power monitoring accuracy	PSU power monitoring improvements include: <ul style="list-style-type: none"> • Dell's power monitoring accuracy is currently 1%, whereas the industry standard is 5% • More accurate reporting of power • Better performance under a power cap
Power capping	Use Dell's systems management to set the power cap limit for your systems to limit the output of a PSU and reduce system power consumption. Dell is the first hardware vendor to leverage Intel Node Manager for circuit-breaker fast capping.
Systems Management	iDRAC Enterprise and Datacenter provides server-level management that monitors, reports and controls power consumption at the processor, memory and system level. Dell OpenManage Power Center delivers group power management at the rack, row, and data center level for servers, power distribution units, and uninterruptible power supplies.
Active power management	Intel Node Manager is an embedded technology that provides individual server-level power reporting and power limiting functionality. Dell offers a complete power management solution comprised of Intel Node Manager accessed through Dell iDRAC9 Datacenter and OpenManage Power Center that allows policy-based management of power and thermal at the individual server, rack, and data center level. Hot spare reduces power consumption of redundant power supplies. Thermal control off a speed optimizes the thermal settings for your environment to reduce fan consumption and lower system power consumption. Idle power enables Dell servers to run as efficiently when idle as when at full workload.
Rack infrastructure	Dell offers some of the industry's highest-efficiency power infrastructure solutions, including:

Table 18. Power tools and technologies (continued)

Feature	Description
	<ul style="list-style-type: none"> • Power distribution units (PDUs) • Uninterruptible power supplies (UPSs) • Energy Smart containment rack enclosures Find additional information at: Power and Cooling .

Power Supply Units

Energy Smart power supplies have intelligent features, such as the ability to dynamically optimize efficiency while maintaining availability and redundancy. Also featured are enhanced power-consumption reduction technologies, such as high-efficiency power conversion and advanced thermal-management techniques, and embedded power-management features, including high-accuracy power monitoring. The table below shows the power supply unit options that are available for the R960.

Table 19. Power supply unit options

Wattage	Frequency	Voltage/Current	Class	Heat dissipation
1100 W mixed mode	50/60 Hz	100–240 Vac/12—3.6 A	Titanium	4100 BTU/hr
	N/A	240 Vdc/5.2 A	N/A	4100 BTU/hr
1400 W mixed mode	50/60 Hz	100–240 Vac/12—8 A	Platinum	5250 BTU/hr
	N/A	240 Vdc/6.6 A	N/A	5250 BTU/hr
1800 W mixed mode	50/60 Hz	200–240 Vac/10 A	Titanium	6750 BTU/hr
	N/A	240 Vdc/8.2 A	N/A	6750 BTU/hr
2400 W mixed mode	50/60 Hz	100–240 Vac/ 16—13.5 A	Platinum	9000 BTU/hr
	N/A	240 Vdc/11.2 A	N/A	9000 BTU/hr
2800 W mixed mode	50/60 Hz	200–240 Vac/15.6 A	Titanium	10,500 BTU/hr
	N/A	240 Vdc/13.6 A	N/A	10,500 BTU/hr
1100 W -48 V DC	NA	(-48) - (-60) Vdc/ 27 A	NA	4267 BTU/hr

NOTE: If a system with AC 2400 W PSUs operates at low line 100-120 Vac, and then the power rating per PSU is degraded to 1400 W.

NOTE: If a system with AC 1400 W or 1100 W PSUs operates at low line 100-120 Vac, and then the power rating per PSU is degraded to 1050 W.





Figure 23. PSU power cords

Table 20. PSU power cords

Form factor	Output	Power cord
Redundant 60 mm	1100 W AC	C13
	1400 W AC	C13
	1800 W AC	C15
	1100 W -48 V DC	LOTES APOW0097
Redundant 86 mm	2400 W AC	C19
	2800 W AC	C21

NOTE: C19 power cord combined with C20 to C21 jumper power cord can be used to adapt 2800 W PSU.

NOTE: C13 power cord combined with C14 to C15 jumper power cord can be used to adapt 1800 W PSU.

Thermal

PowerEdge servers have an extensive collection of sensors that automatically track thermal activity, which helps regulate temperature thereby reducing server noise and power consumption.

Thermal design

Thermal management of the platform helps deliver high performance with the right amount of cooling to components, while maintaining the lowest fan speeds possible. This is done across a wide range of ambient temperatures from 10°C to 35°C (50°F to 95°F) and to extended ambient temperature ranges.

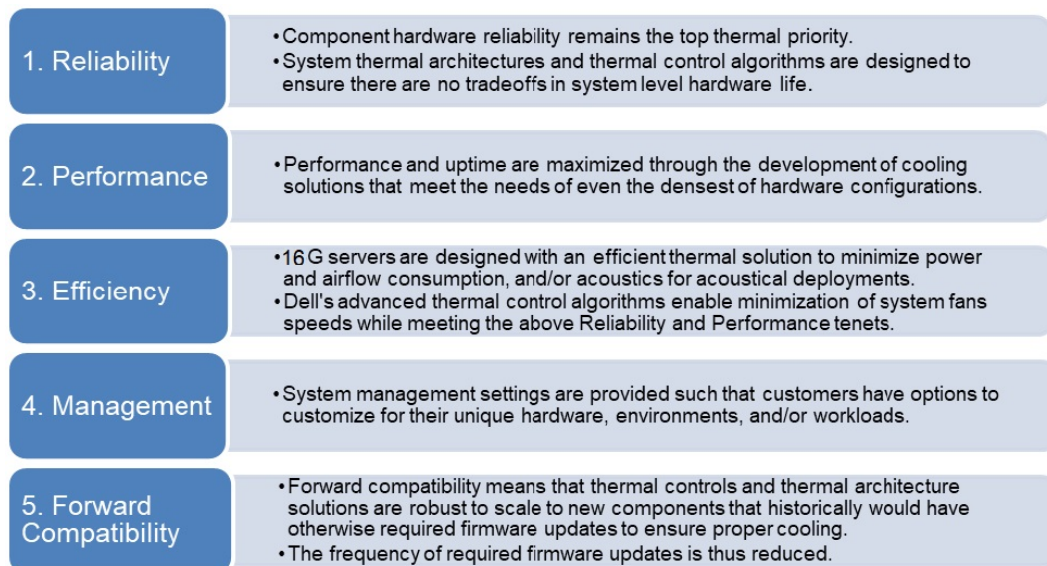


Figure 24. Thermal design characteristics

The thermal design of the PowerEdge R960 reflects the following:

- Optimized thermal design: The system layout is architected for optimum thermal design.
- System component placement and layout are designed to provide maximum airflow coverage to critical components with minimum expense of fan power.
- Comprehensive thermal management: The thermal control system regulates the fan speed based on several different responses from all system-component temperature sensors, and inventory for system configurations. Temperature monitoring includes components such as processors, DIMMs, chipset, the inlet air ambient, hard disk drives, and OCP.
- Open and closed loop thermal fan speed control: Open loop thermal control uses system configuration to determine fan speed based on inlet air ambient temperature. Closed loop thermal control method uses feedback temperatures to dynamically determine proper fan speeds.
- User-configurable settings: With the understanding and realization that every customer has unique set of circumstances or expectations from the system, in this generation of servers, we have introduced limited user- configurable settings residing in the iDRAC BIOS setup screen. For more information, see the Dell PowerEdge R960 Installation and Service Manual at [PowerEdge Manuals](#) and “Advanced Thermal Control: Optimizing across Environments and Power Goals” on Dell.com.
- Cooling redundancy: The R960 allows N+1 fan redundancy, allowing continuous operation with one fan failure in the system.
- Environmental Specifications: The optimized thermal management makes the R960 reliable under a wide range of operating environments.

Acoustics

Acoustical configurations of R960

Dell PowerEdge R960 is a rack or tower server appropriate for attended data center environment. However, lower acoustical output is attainable with proper hardware or software configurations.

Table 21. Configurations tested for acoustical experience

Configuration	Quietest	HCI	Data Management	Machine Learning
CPU TDP	Intel (Gold 6) 195 W	Intel (Gold 6) 250 W	Intel (Gold 6) 250 W	Intel (Platinum 8) 350 W
CPU Quantity	4	4	4	4
RDIMM Memory	16G DDR5 4800 MHz	64G DDR5 4800 MHz	64G DDR5 4800 MHz	64G DDR5 4800 MHz
Memory Quantity	4	32	48	64
Backplane Type	2.5" x 32 BP	2.5" x 32 BP	2.5" x 16 BP	2.5" x 32 BP

Table 21. Configurations tested for acoustical experience (continued)

Configuration	Quietest	HCI	Data Management	Machine Learning
HDD Type	SAS TOSHIBA AL15SE 2.5" 600 GB	SAS TOSHIBA AL15SE 2.5" 600 GB	SAS TOSHIBA AL15SE 2.5" 1.2 TB	SAS Seagate Skybolt 2.5" 1.8 TB
HDD Quantity	32	32	16	32
M.2 Drives	Hynix NVMe 480G	Hynix NVMe 480G	Hynix NVMe 480G	Hynix NVMe 480G
M.2 Quantity	1	1	1	1
PSU Type	ARTESYN 2400 W	LITEON 2800 W	ARTESYN 2400 W	LITEON 2800 W
PSU Quantity	4	4	4	4
OCP	X	Intel OCP3 10G 2-port	Intel OCP3 10G 2-port	Intel OCP3 10G 2-port
PCI 1	X	X	X	X
PCI 2	X	X	NVIDIA A16 250W	X
PCI 3	X	X	X	X
PCI 4	X	X	X	X
PCI 5	X	X	X	X
PCI 6	X	X	X	X
PCI 7	X	X	X	X
PCI 8	X	X	X	X
PCI 9	X	X	X	X
PCI 10	X	X	NVIDIA A16 250 W	X
PCI 11	X	X	X	X
PCI 12	X	X	X	X
PERC	Front H755	Front H755	Front H755	Front H755

Table 22. Acoustical experience of R960 configurations

Configuration		Quietest	HCI	Data Management	Machine Learning
Acoustical Performance: Idle/ Operating @ 25°C Ambient					
L _{wA,m} (B)	Idle ⁽⁴⁾	5.4	6.0	6.0	5.6
	Operating/Customer usage operating ⁽⁵⁾⁽⁶⁾	5.7	6.3	7.5	6.7
K _v (B)	Idle ⁽⁴⁾	0.4	0.4	0.4	0.4
	Operating/Customer usage operating ⁽⁵⁾⁽⁶⁾	0.4	0.4	0.4	0.4
L _{pA,m} (dB)	Idle ⁽⁴⁾	39	44	44	41
	Operating/Customer usage operating ⁽⁵⁾⁽⁶⁾	43	47	60	53
Prominent discrete tones ⁽³⁾		Prominence ratio < 15 dB			
Acoustical Performance: Idle @ 28°C Ambient					
L _{wA,m} ⁽¹⁾ (B)		6.1	6.6	6.9	6.4
K _v (B)		0.4	0.4	0.4	0.4
L _{pA,m} ⁽²⁾ (dB)		45	51	54	49

Table 22. Acoustical experience of R960 configurations (continued)

Configuration	Quietest	HCI	Data Management	Machine Learning
Acoustical Performance: Max. loading @ 35°C Ambient				
$L_{wA,m}^{(1)}$ (B)	7.5	7.8	9.0	9.2
K_v (B)	0.4	0.4	0.4	0.4
$L_{pA,m}^{(2)}$ (dB)	60	63	74	77

⁽¹⁾ $L_{wA,m}$: The declared mean A-weighted sound power level (L_{wA}) is calculated per section 5.2 of ISO 9296 (2017) with data collected using the methods that are described in ISO 7779 (2010). Engineering data presented here may not be fully compliant with the ISO 7779 declaration requirement.

⁽²⁾ $L_{pA,m}$: The declared mean A-weighted emission sound pressure level is at the bystander position per section 5.3 of ISO 9296 (2017) and measured using methods that are described in ISO 7779 (2010). The system is placed in a 24U rack enclosure, 25 cm above a reflective floor. Engineering data presented here may not be fully compliant with the ISO 7779 declaration requirement.

⁽³⁾Prominent tones: Criteria of Annex D of ECMA-74 and the Prominence Ratio method of ECMA-418 are followed to determine if discrete tones are prominent and to report them, if so.

⁽⁴⁾Idle mode: The steady-state condition in which the server is energized but not operating any intended function.

⁽⁵⁾Operating mode: The maximum of the steady state acoustical output at 50% of CPU TDP or active storage drives for the respective sections of Annex C of ECMA-74.

⁽⁶⁾ Customer Usage Operating mode: The operating mode is represented by the maximum of the steady state acoustical output at 25%~30% of CPU TDP, 2.5%~10% IOPs load, and >80% GPU load as the components showed in the above configurations.

Rack, rails, and cable management

Topics:

- [Rails and cable management information](#)

Rails and cable management information

The rail offerings for the PowerEdge R960 consist of one sliding type. The cable management offerings consist of an optional cable management arm (CMA) and an optional strain relief bar (SRB).

See the *Enterprise Systems Rail Sizing and Rack Compatibility Matrix* available at [Rack Compatibility Matrix](#) for information regarding:

- Specific details about rail types.
- Rail adjustability ranges for various rack mounting flange types.
- Rail depth with and without cable management accessories.
- Rack types that are supported for various rack mounting flange types.

Key factors governing proper rail selection include the following:

- Spacing between the front and rear mounting flanges of the rack.
- Type and location of any equipment that is mounted in the back of the rack such as power distribution units (PDUs).
- Overall depth of the rack.

Sliding rails features summary

The sliding rails allow the system to be fully extended out of the rack for service. There is one type of sliding rails available, Stab-in/Drop-in sliding rails. The sliding rails are available with or without the optional cable management arm (CMA) or strain relief bar (SRB).

B19 Stab-in/Drop-in sliding rails for 4-post racks

- Supports drop-in or stab-in installation of the chassis to the rails.
- Support for tool-less installation in 19" EIA-310-E compliant square, unthreaded round hole racks including all generations of the Dell racks. Also supports tool-less installation in threaded round hole 4-post racks.
- Support for tool-less installation in Dell Titan or Titan-D racks.
- Support full extension of the system out of the rack to allow serviceability of key internal components.
- Support for an optional cable management arm (CMA).
- Support for optional strain relief bar (SRB).

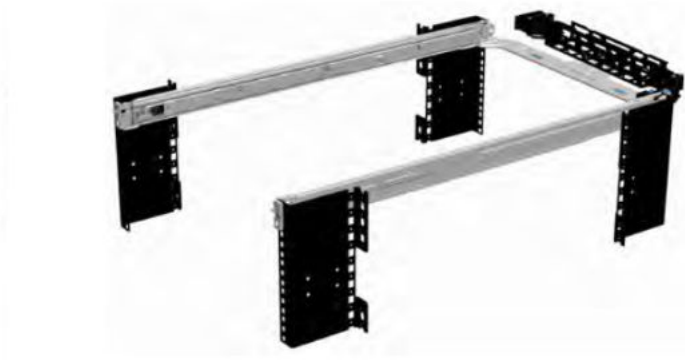


Figure 25. Sliding rails with optional CMA



Figure 26. Sliding rails with optional SRB

Scan the QR code for the documentation and trouble-shooting information regarding the installation procedures for Drop-in/Stab-in rail types.

Installation in the Dell Titan or Titan-D racks

For tool-less installation in Titan or Titan-D racks, the Stab-in/Drop-in sliding rails (B19) must be used. This rail collapses down sufficiently to fit in the rack with mounting flanges that are spaced about 24 inches apart from front to back. The Stab-in/Drop-in sliding rail allows bezels of the servers and storage systems to be aligned when installed in these racks.

Cable management arm (CMA)

The optional cable management arm (CMA) organizes and secures the cords and cables exiting the back of the systems. It unfolds to allow the systems to extend out of the rack without having to detach the cables. Some key features of the CMA include:

- Large U-shaped baskets to support dense cable loads.

- Open vent pattern for optimal airflow.
- Ability to mount on either side by swinging the spring-loaded brackets from one side to the other.
- Utilizes hook-and-loop straps rather than plastic tie wraps to eliminate the risk of cable damage during cycling.
- Includes a low-profile fixed tray to both support and retain the CMA in its fully closed position.
- Both the CMA and the tray mount without the use of tools by simple and intuitive snap-in designs.

For systems with one power supply unit (PSU), it is recommended to mount on the side opposite to that of the power supply to allow easier access to it and the rear drives (if applicable) for service or replacement.



Figure 27. Sliding rails with CMA

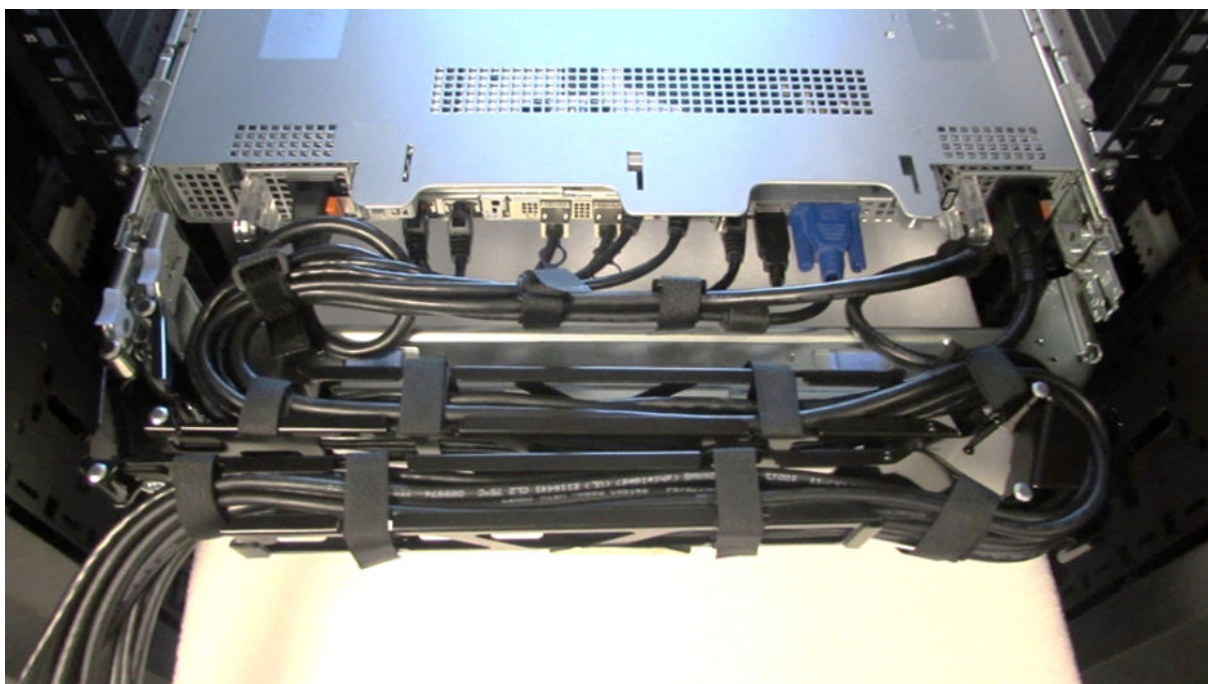


Figure 28. CMA Cabling

Strain Relief Bar (SRB)

The optional strain relief bar (SRB) for the PowerEdge R960 organizes and supports cable connections at the rear end of the server to avoid damage from bending.

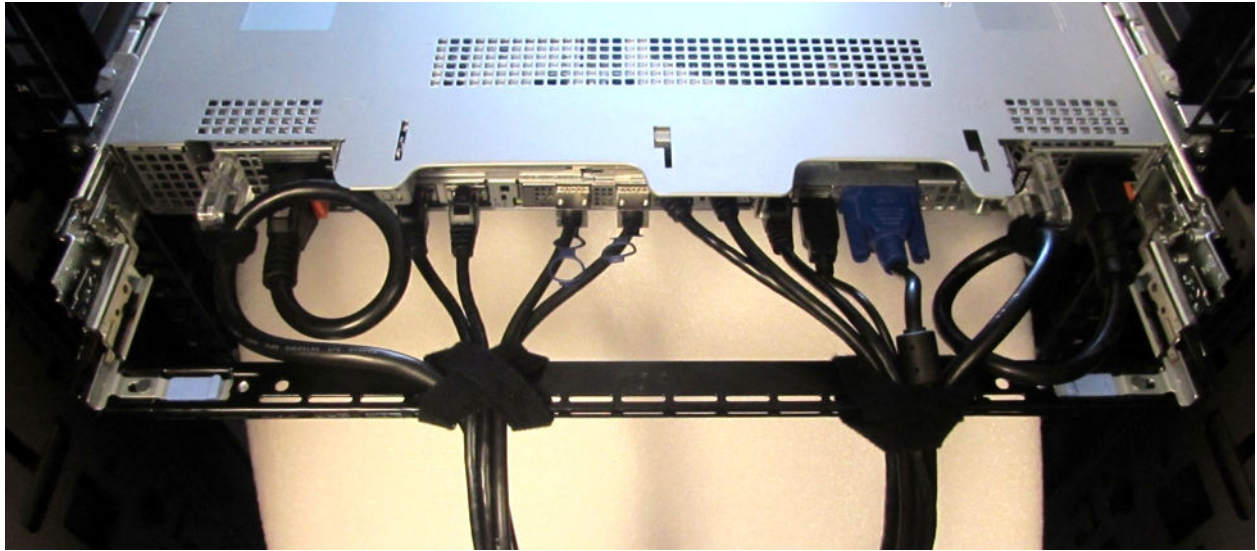


Figure 29. Cabled strain relief bar

- Tool-less attachment to the rails
- Two depth positions to accommodate various cable loads and rack depths
- Supports cable loads and controls stresses on server connectors
- Cables can be segregated into discrete purpose-specific bundles

Rack Installation

Drop-in design means that the system is installed vertically into the rails by inserting the standoffs on the sides of the system into the J-slots in the inner rail members with the rails in the fully extended position. The recommended method of installation is to first insert the rear standoffs on the system into the rear J-slots on the rails to free up a hand and then rotate the system down into the remaining J-slots while using the free hand to hold the rail against the side of the system.

Stab-in design means that the inner (chassis) rail members must first be attached to the sides of the system and then inserted into the outer (cabinet) members installed in the rack.

Installing the system into the rack (option A: Drop-In)

1. Pull the inner rails out of the rack until they lock into place.

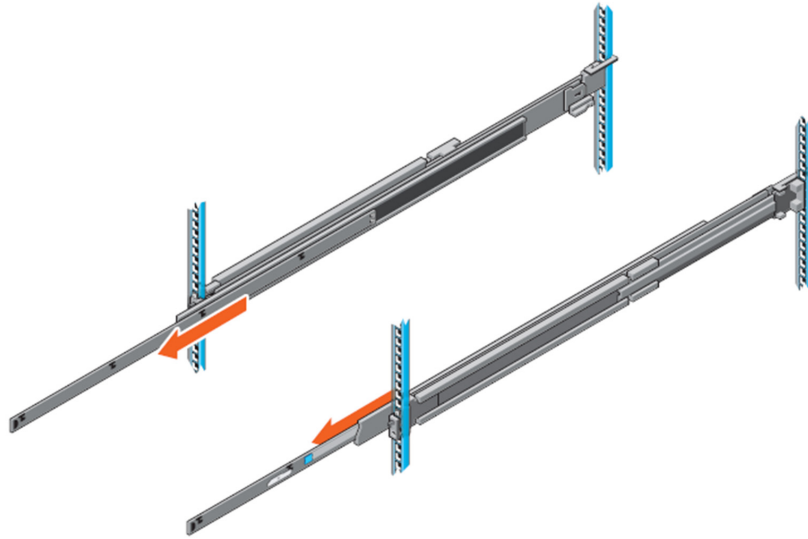


Figure 30. Pull out inner rail

2. Locate the rear rail standoff on each side of the system and lower them into the rear J-slots on the slide assemblies.
3. Rotate the system downward until all the rail standoffs are seated in the J-slots.

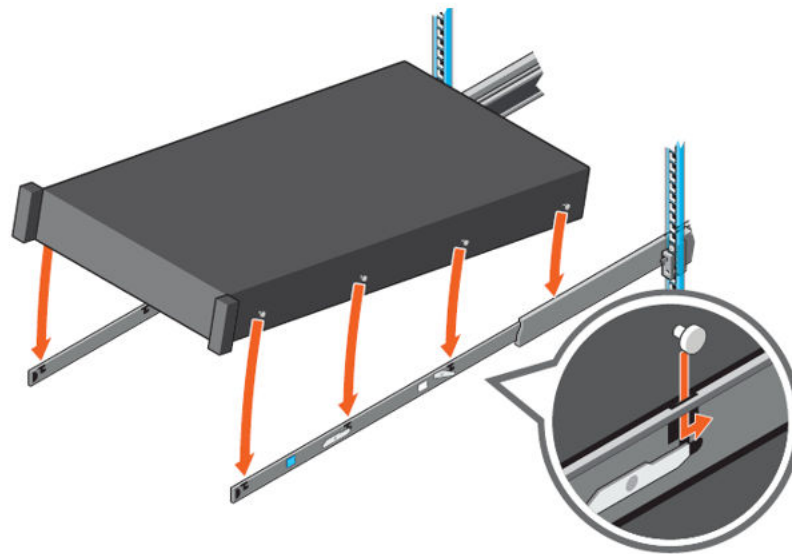


Figure 31. Rail standoffs seated in J-slots

4. Push the system inward until the lock levers click into place.
5. Pull the blue side release lock tabs forward or backward on both rails and slide the system into the rack until the system is in the rack.

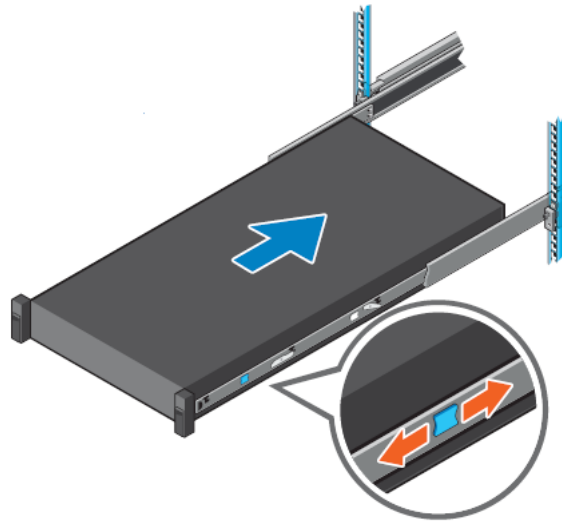


Figure 32. Slide system into the rack

Installing the system into the rack (option B: Stab-In)

1. Pull the intermediate rails out of the rack until they lock into place.
2. Release the inner rail lock by pulling forward on the white tabs and sliding the inner rail out of the intermediate rails.

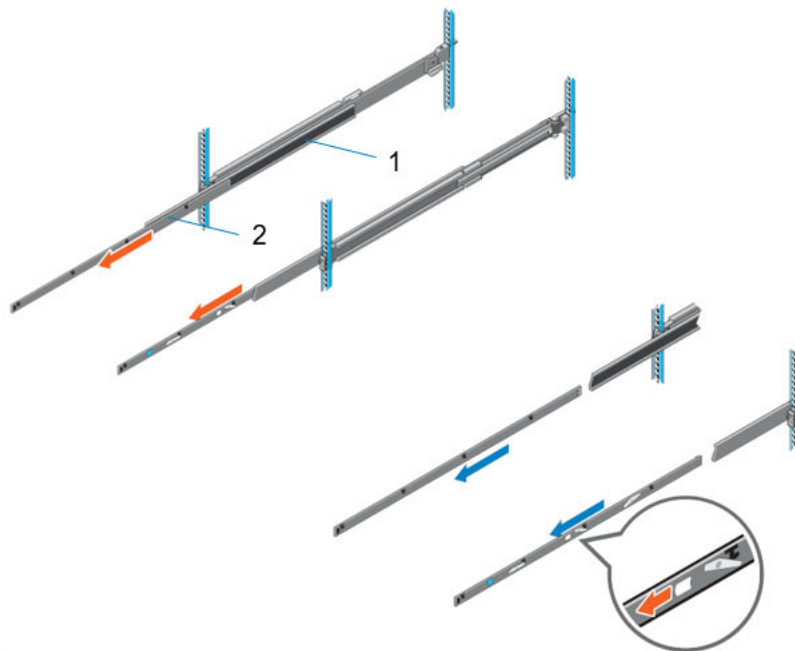


Figure 33. Pull out the intermediate rail

Table 23. Rail component label

Number	Component
1	Intermediate rail
2	Inner rail

3. Attach the inner rails to the sides of the system by aligning the J-slots on the rail with the standoffs on the system and sliding forward on the system until they lock into place.

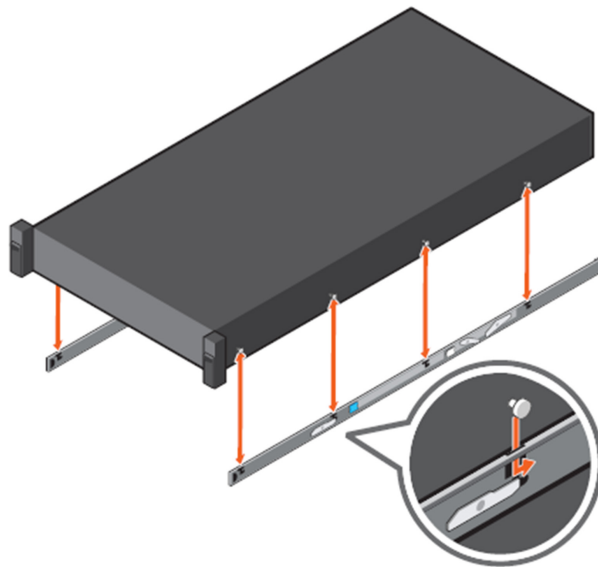


Figure 34. Attach the inner rails to the system

4. With the intermediate rails extended, install the system into the extended rails.

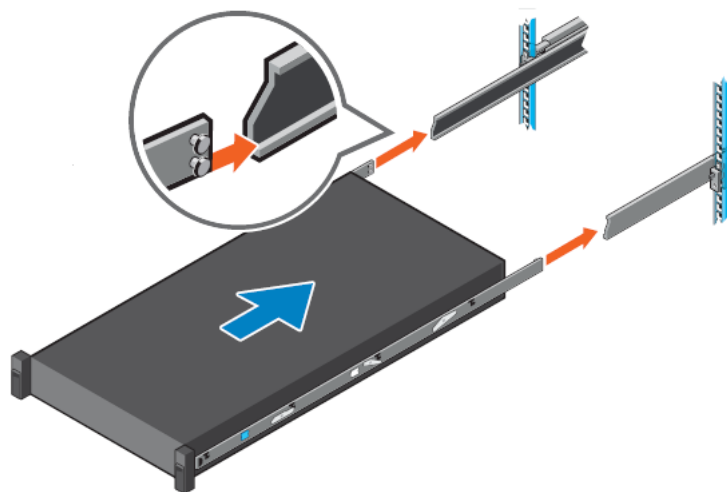


Figure 35. Install system into the extended rails

5. Pull blue slide release lock tabs forward or backward on both rails, and slide the system into the rack.

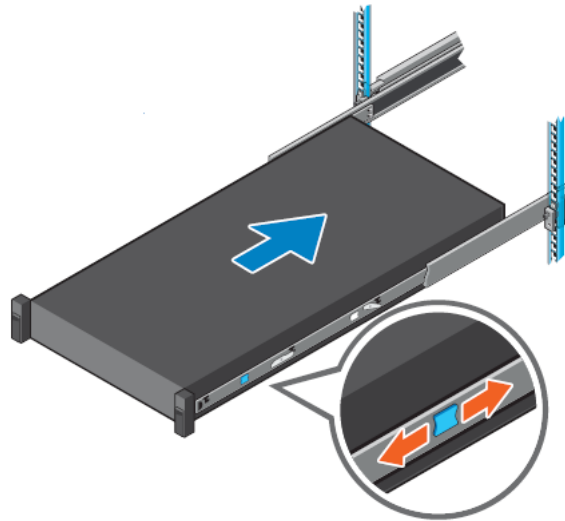


Figure 36. Slide system into the rack

Operating Systems and Virtualization

Topics:

- [Supported Operating Systems](#)

Supported Operating Systems

The PowerEdge system supports the following operating systems:

- Canonical® Ubuntu® Server LTS
- Microsoft® Windows Server® with Hyper-V
- Red Hat® Enterprise Linux
- SUSE® Linux Enterprise server
- VMware® ESXi®

Links to specific OS versions and editions, certification matrices, Hardware Compatibility Lists (HCL) portal, and Hypervisor support are available at [Dell Enterprise Operating Systems](#).

Dell OpenManage Systems Management

Dell delivers management solutions that help IT administrators effectively deploy, update, monitor, and manage IT assets. OpenManage solutions and tools enable you to quickly respond to problems by helping them to manage Dell servers efficiently; in physical, virtual, local, and remote environments; all without the need to install an agent in the operating system.

The OpenManage portfolio includes:

- Innovative embedded management tool - integrated Dell Remote Access Controller (iDRAC)
- Consoles - OpenManage Enterprise
- Extensible with plug-ins - OpenManage Power Manager
- Update tools - Repository Manager

Dell has developed comprehensive systems management solutions that are based on open standards and has integrated with management consoles from partners such as Microsoft and VMware, allowing advanced management of Dell servers. Dell management capabilities extend to offerings from the industry's top systems management vendors and frameworks such as Ansible, Splunk, and ServiceNow. OpenManage tools automate the full span of server life cycle management activities along with powerful RESTful APIs to script or integrate with your choice of frameworks.

For more information about the entire OpenManage portfolio, see:

- The latest [Dell Systems Management Overview Guide](#).

Topics:

- [Integrated Dell Remote Access Controller \(iDRAC\)](#)
- [Systems Management software support matrix](#)

Integrated Dell Remote Access Controller (iDRAC)

iDRAC9 delivers advanced, agent-free, local and remote server administration. Embedded in every PowerEdge server, iDRAC9 provides a secure means to automate a multitude of common management tasks. Because iDRAC is embedded within every PowerEdge server, there is no additional software to install; just plug in power and network cables, and iDRAC is ready to go. Even before installing an operating system (operating system) or hypervisor, IT administrators have a complete set of server management features at their fingertips.

With iDRAC9 in-place across the Dell PowerEdge portfolio, the same IT administration techniques and tools can be applied throughout. This consistent management platform allows easy scaling of PowerEdge servers as an organization's infrastructure grows. Customers can use the iDRAC RESTful API for the latest in scalable administration methods of PowerEdge servers. With this API, iDRAC enables support for the Redfish standard and enhances it with Dell extensions to optimize at-scale management of PowerEdge servers. By having iDRAC at the core, the entire OpenManage portfolio of Systems Management tools allows every customer to tailor an effective, affordable solution for any size environment.

Zero Touch Provisioning (ZTP) is embedded in iDRAC. ZTP - Zero Touch Provisioning is Intelligent Automation Dell's agent-free management puts IT administrators in control. Once a PowerEdge server is connected to power and networking, that system can be monitored and fully managed, whether you're standing in front of the server or remotely over a network. In fact, with no need for software agents, an IT administrator can: • Monitor • Manage • Update • Troubleshoot and remediate Dell servers With features like zero-touch deployment and provisioning, iDRAC Group Manager, and System Lockdown, iDRAC9 is purpose-built to make server administration quick and easy. For those customers whose existing management platform utilizes in-band management, Dell does provide iDRAC Service Module, a lightweight service that can interact with both iDRAC9 and the host operating system to support legacy management platforms.

When ordered with DHCP enabled from the factory, PowerEdge servers can be automatically configured when they are initially powered up and connected to your network. This process uses profile-based configurations that ensure each server is configured per your specifications. This feature requires an iDRAC Enterprise license.

iDRAC9 offers following license tiers:

Table 24. iDRAC9 license tiers

License	Description
iDRAC9 Basic	<ul style="list-style-type: none"> Available only on 100-500 series rack/tower Basic instrumentation with iDRAC web UI For cost conscious customers that see limited value in management
iDRAC9 Express	<ul style="list-style-type: none"> Default on 600+ series rack/tower, modular, and XR series Includes all features of Basic Expanded remote management and server life-cycle features
iDRAC9 Enterprise	<ul style="list-style-type: none"> Available as an upsell on all servers Includes all features of Basic and Express. Includes key features such as virtual console, AD/LDAP support, and more Remote presence features with advanced, Enterprise-class, management capabilities
iDRAC9 Datacenter	<ul style="list-style-type: none"> Available as an upsell on all servers Includes all features of Basic, Express, and Enterprise. Includes key features such as telemetry streaming, Thermal Manage, automated certificate management, and more Extended remote insight into server details, focused on high end server options, granular power, and thermal management

For a full list of iDRAC features by license tier, see [Integrated Dell Remote Access Controller 9 User's Guide](#) at [Dell.com](#).

For more details on iDRAC9 including white papers and videos, see:

- [Support for Integrated Dell Remote Access Controller 9 \(iDRAC9\)](#) on the [Knowledge Base](#) page at [Dell.com](#)

Systems Management software support matrix

Table 25. Systems Management software support matrix

Categories	Features	PE mainstream
Embedded Management and In-band Services	iDRAC9 (Express, Enterprise, and Datacenter licenses)	Supported
	OpenManage Mobile	Supported
	OM Server Administrator (OMSA)	Supported
	iDRAC Service Module (iSM)	Supported
	Driver Pack	Supported
Change Management	Update Tools (Repository Manager, DSU, Catalogs)	Supported
	Server Update Utility	Supported
	Lifecycle Controller Driver Pack	Supported
	Bootable ISO	Supported
Console and Plug-ins	OpenManage Enterprise	Supported
	Power Manager Plug-in	Supported
	Update Manager Plug-in	Supported
	SupportAssist Plug-in	Supported
	CloudIQ	Supported
Integrations and connections	OM Integration with VMware Vcenter/vROps	Supported
	OM Integration with Microsoft System Center (OMIMSC)	Supported
	Integrations with Microsoft System Center and Windows Admin Center (WAC)	Supported

Table 25. Systems Management software support matrix (continued)

Categories	Features	PE mainstream
	ServiceNow	Supported
	Ansible	Supported
	Third-party Connectors (Nagios, Tivoli, Microfocus)	Supported
Security	Secure Enterprise Key Management	Supported
	Secure Component Verification	Supported
Standard operating system	Red Hat Enterprise Linux, SUSE, Windows Server 2021 Ubuntu, CentOS	Supported (Tier-1)

Appendix A: Additional specifications

Topics:

- Chassis dimension
- Chassis weight
- NIC port specifications
- Video specifications
- USB Ports
- PSU rating
- Environmental specifications

Chassis dimension

The R960 has the following dimensions:

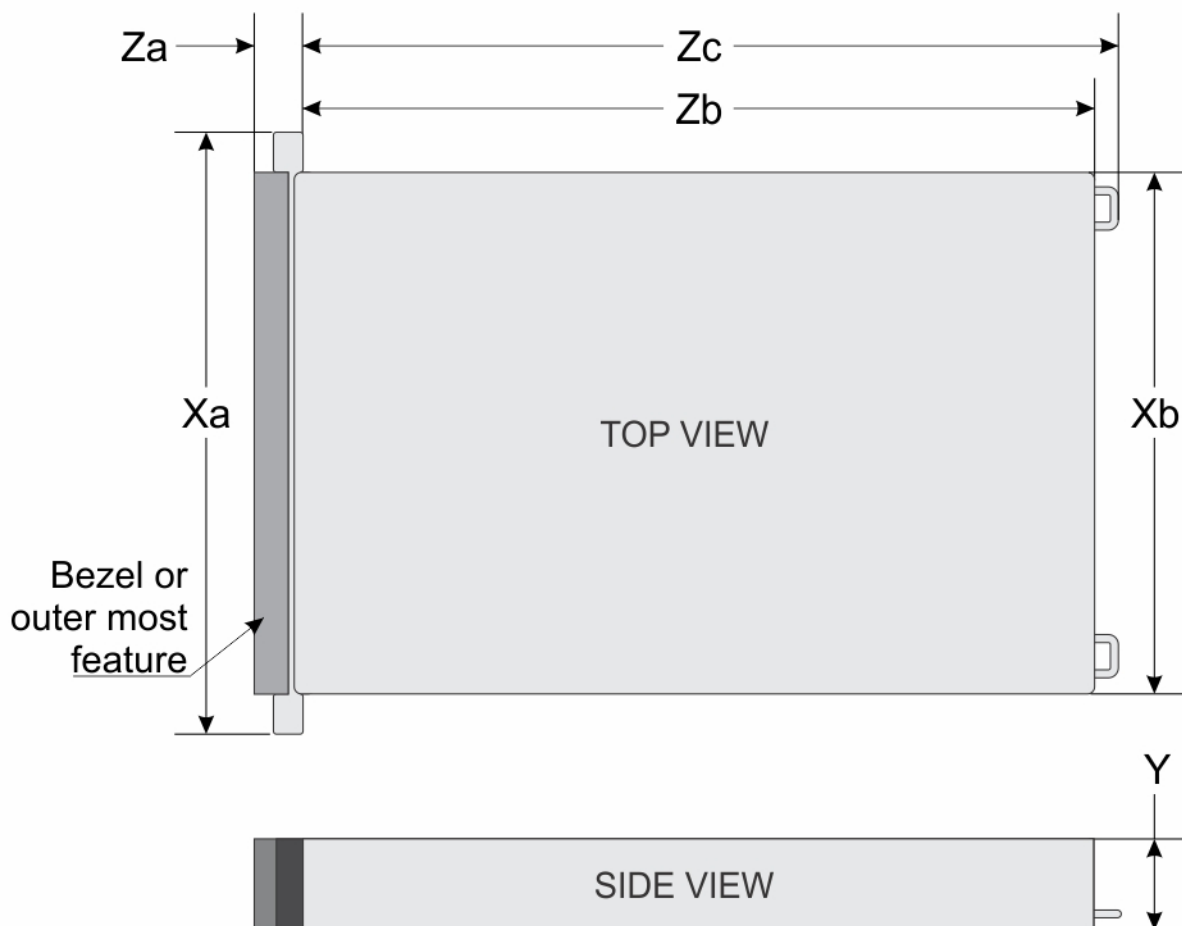


Figure 37. Chassis dimensions

Table 26. Chassis dimensions

Model number	Xa	Xb	Y	Za with bezel	Za without bezel	Zb	Zc	Max Sys Wgt	Chassis
R960	482 mm	444 mm	174.3 mm	36 mm	22 mm	844.74 mm	847.195 mm	60.2 kg	4U

Chassis weight

Table 27. Chassis weight


System Configuration	Maximum Weight
A server with fully populated drives	60.2 kg (132.71 lbs)
A server without drives and PSU installed	N/A

NIC port specifications

The system supports up to two 10/100/1000 Mbps Network Interface Controller (NIC) ports embedded on the LAN on Motherboard (LOM) card and integrated on the optional OCP cards.

Table 28. NIC port specification for the system

Feature	Specifications
LOM card (optional)	1 GbE x 2
OCP card (OCP 3.0) (Optional)	1 GbE x 4, 10 GbE x 2, 10 GbE x 4, 25 GbE x 2, 25 GbE x 4, 100 GbE x 2

 **NOTE:** The system allows either LOM card or an OCP card or both to be installed in the system.

Video specifications

The PowerEdge R960 system supports integrated Matrox G200 graphics controller with 16 MB of video frame buffer.

Table 29. Video specifications for R960

Resolution	Refresh rate (Hz)	Color depth (bits)
1024 x 768	60	8, 16, 32
1280 x 800	60	8, 16, 32
1280 x 1024	60	8, 16, 32
1360 x 768	60	8, 16, 32
1440 x 900	60	8, 16, 32
1600 x 900	60	8, 16, 32
1600 x 1200	60	8, 16, 32
1680 x 1050	60	8, 16, 32
1920 x 1080	60	8, 16, 32
1920 x 1200	60	8, 16, 32

USB Ports

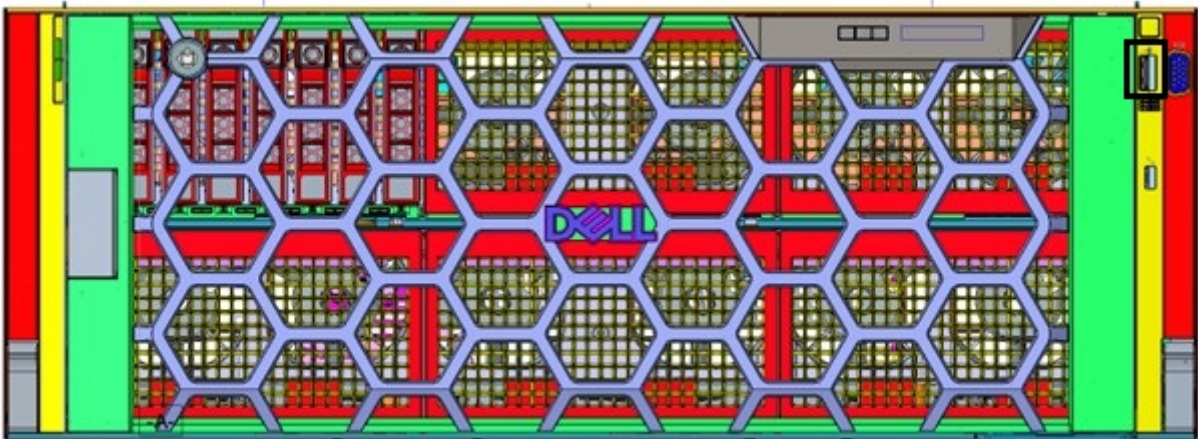


Figure 38. Front USB Port

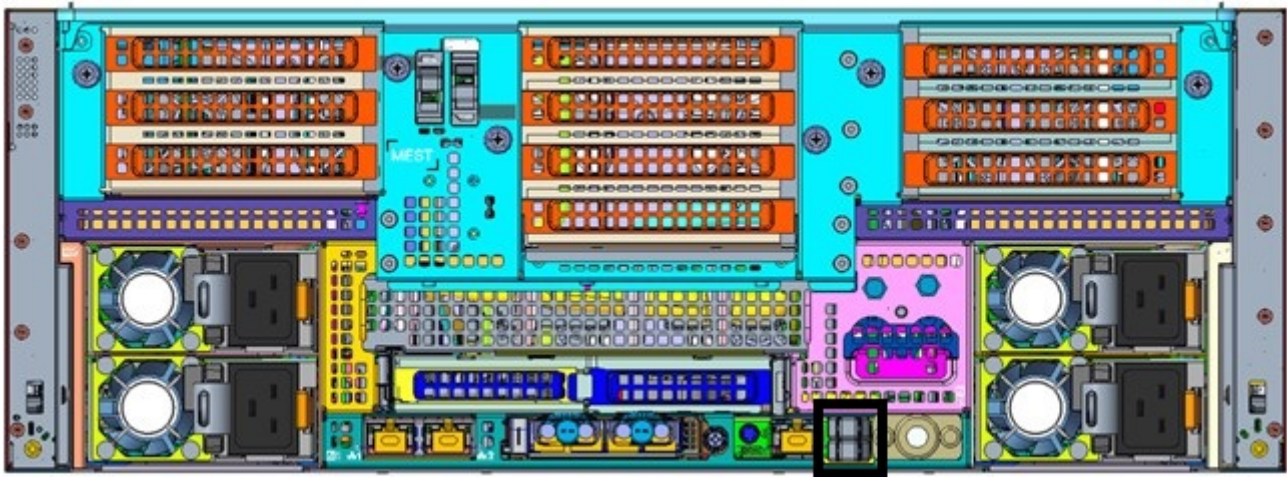


Figure 39. Rear USB Port

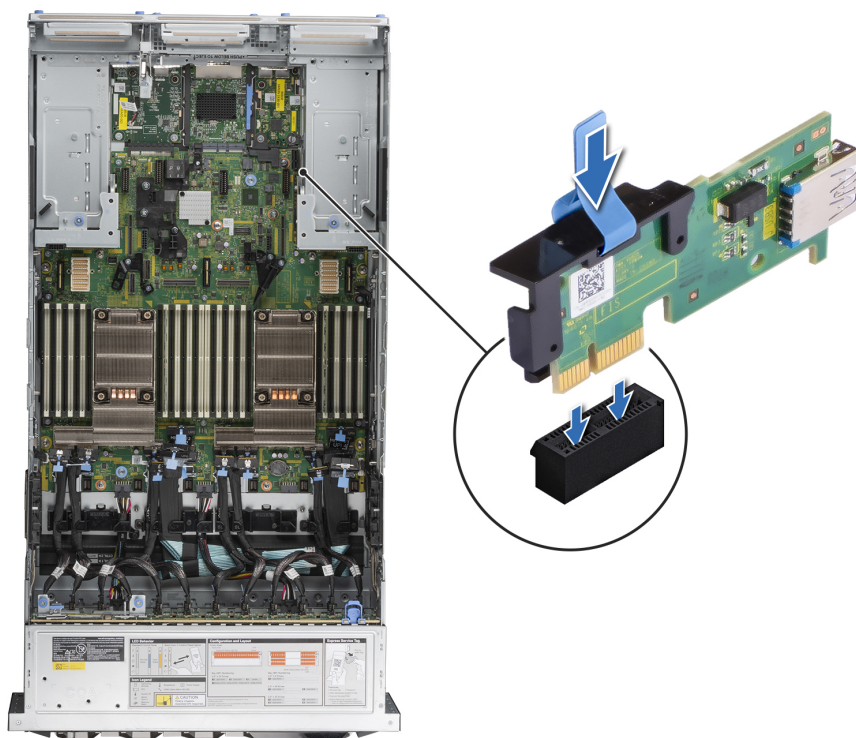


Figure 40. Internal USB Port

Table 30. Systems USB specifications

Front		Rear		Internal	
USB port type	No. of ports	USB port type	No. of ports	USB port type	No. of ports
USB x.2.0 – compliant port	1	USB x.2.0 – compliant port	1	USB x.3.0 – compliant port	1
		USB x.3.0 – compliant port	1		

PSU rating

Below table lists the power capacity the PSUs in high/low line operation mode.

Table 31. PSUs highline and lowline ratings

—	1100 W Titanium	1400 W Platinum	1800 W Titanium	2400 W Platinum	2800 W Titanium	1100 W -48 V DC
Peak Power (Highline/-72 VDC)	1870 W	2380 W	3060 W	4080 W	4760 W	N/A
Highline/-72 VDC	1100 W	1400 W	1800 W	2400 W	2800 W	N/A
Peak Power (Lowline/-40 VDC)	1785 W	1785 W	N/A	2380 W	N/A	N/A
Lowline/-40 VDC	1050 W	1050 W	N/A	1400 W	N/A	N/A

Table 31. PSUs highline and lowline ratings (continued)

—	1100 W Titanium	1400 W Platinum	1800 W Titanium	2400 W Platinum	2800 W Titanium	1100 W -48 V DC
Highline 240 VDC	1100 W	1400 W	1800 W	2400 W	2800 W	N/A
DC (-48)-(-60) VDC	N/A	N/A	N/A	N/A	N/A	1100 W

The PowerEdge R960 supports up to four AC power supplies with 2+2 redundancy, autosensing, and auto switching capability.

A PSU Mismatch occurs when a PSU or a set of PSUs is incompatible with other PSUs in the system. The iDRAC determines PSU compatibility based on a set of tests at both iDRAC boot and when a PSU is hot-plugged into the system. If the platform supports more than 2 PSUs, half the PSUs should be tested the compatibility.

If 2+2 PSUs are present during iDRAC boot, a comparison is made between the wattage capacities of the two sets of PSUs. In the event that the two sets of PSUs wattages don't match, the larger capacity of the two sets of PSUs is enabled. Also, there is a PSU mismatch warning displayed in BIOS, iDRAC, or on the System LCD.

If the second set of PSUs is added at run-time, in order for that second set of PSUs to be enabled, the wattage capacity of the second set of PSUs must equal to the first set of PSU. Otherwise, the second set of PSUs will be flagged as unmatched in iDRAC and the second PSU will not be enabled.

Dell PSUs have achieved Platinum efficiency levels as shown in the table below.

Table 32. PSU efficiency level

Efficiency Targets by Load						
Form factor	Output	Class	10%	20%	50%	100%
Redundant 60 mm	1100 W AC	Titanium	90.00%	94.00%	96.00%	91.50%
	1400 W AC	Platinum	89.00%	93.00%	94.00%	91.50%
	1800 W AC	Titanium	90.00%	94.00%	96.00%	94.00%
	1100 W -48 V DC	N/A	85.00%	90.00%	92.00%	90.00%
Redundant 86 mm	2400 W AC	Platinum	89.00%	93.00%	94.00%	91.50%
	2800 W AC	Titanium	90.00%	94.00%	96.00%	94%

Environmental specifications


 **NOTE:** For additional information about environmental certifications, refer to the *Product Environmental Datasheet* located with the *Documentation* on [Dell Support](#).

Table 33. Continuous Operation Specifications for ASHRAE A2

Temperature	Specifications
Allowable continuous operations	
Temperature range for altitudes < 900 m (< 2953 ft)	10–35°C (50–95°F) with no direct sunlight on the equipment
Humidity percent range (non-condensing at all times)	8% RH with -12°C (10.4°F) minimum dew point to 80% RH with 21°C (69.8°F) maximum dew point
Operational altitude de-rating	Maximum temperature is reduced by 1°C/300 m (1.8°F/984 Ft) above 900 m (2953 Ft)

Table 34. Continuous Operation Specifications for ASHRAE A3

Temperature	Specifications
Allowable continuous operations	
Temperature range for altitudes ≤ 900 m (≤ 2953 ft)	5–40°C (41–104°F) with no direct sunlight on the equipment
Humidity percent range (non-condensing at all times)	8% RH with -12°C (10.4°F) minimum dew point to 85% RH with 24°C (75.2°F) maximum dew point
Operational altitude de-rating	Maximum temperature is reduced by 1°C/175 m (1.8°F/574 Ft) above 900 m (2953 Ft)

Table 35. Continuous Operation Specifications for ASHRAE A4

Temperature	Specifications
Allowable continuous operations	
Temperature range for altitudes ≤ 900 m (≤ 2953 ft)	5–45°C (41–113°F) with no direct sunlight on the equipment
Humidity percent range (non-condensing at all times)	8% RH with -12°C (10.4°F) minimum dew point to 90% RH with 24°C (75.2°F) maximum dew point
Operational altitude de-rating	Maximum temperature is reduced by 1°C/125 m (1.8°F/410 Ft) above 900 m (2953 Ft)

Table 36. Common Environmental Specifications for ASHRAE A2, A3 and A4


Temperature	Specifications
Allowable continuous operations	
Maximum temperature gradient (applies to both operation and non-operation)	20°C in an hour* (36°F in an hour) and 5°C in 15 minutes (9°F in 15 minutes), 5°C in an hour* (9°F in an hour) for tape hardware  NOTE: * Per ASHRAE thermal guidelines for tape hardware, these are not instantaneous rates of temperature change.
Non-operational temperature limits	-40 to 65°C (-40 to 149°F)
Non-operational humidity limits (non-condensing at all times)	5% to 95% RH with 27°C (80.6°F) maximum dew point
Maximum non-operational altitude	12,000 meters (39,370 feet)
Maximum operational altitude	3,050 meters (10,006 feet)

Table 37. Maximum vibration specifications

Maximum vibration	Specifications
Operating	0.21 G _{rms} at 5 Hz to 500 Hz for 10 minutes (all operation orientations)
Storage	1.88 G _{rms} at 10 Hz to 500 Hz for 15 minutes (all six sides tested)

Table 38. Maximum shock pulse specifications

Maximum shock pulse	Specifications
Operating	Six consecutively executed shock pulses in the positive and negative x, y, and z axis of 6 G for up to 11 ms
Storage	Six consecutively executed shock pulses in the positive and negative x, y, and z axis (one pulse on each side of the system) of 71 G for up to 2 ms

Particulate and gaseous contamination specifications

The following table defines the limitations that help avoid any equipment damage or failure from particulates and gaseous contamination. If the levels of particulates or gaseous pollution exceed the specified limitations and result in equipment damage or failure, you may need to rectify the environmental conditions. Remediation of environmental conditions is the responsibility of the customer.

Table 39. Particulate contamination specifications

Particulate contamination	Specifications
Air filtration	Data center air filtration as defined by ISO Class 8 per ISO 14644-1 with a 95% upper confidence limit i NOTE: This condition applies to data center environments only. Air filtration requirements do not apply to IT equipment designed to be used outside a data center, in environments such as an office or factory floor. i NOTE: Air entering the data center must have MERV11 or MERV13 filtration.
Conductive dust	Air must be free of conductive dust, zinc whiskers, or other conductive particles i NOTE: This condition applies to data center and non-data center environments.
Corrosive dust	<ul style="list-style-type: none">Air must be free of corrosive dustResidual dust present in the air must have a deliquescent point less than 60% relative humidity i NOTE: This condition applies to data center and non-data center environments.
Walk-Up Edge Data Center or Cabinet (sealed, closed loop environment)	Filtration is not required for cabinets that are anticipated to be opened 6 times or less per year. Class 8 per ISO 1466-1 filtration as defined above is required otherwise i NOTE: In environments commonly above ISA-71 Class G1 or that may have known challenges, special filters may be required.

Table 40. Gaseous contamination specifications

Gaseous contamination	Specifications
Copper coupon corrosion rate	<300 Å/month per Class G1 as defined by ANSI/ISA71.04-2013
Silver coupon corrosion rate	<200 Å/month as defined by ANSI/ISA71.04-2013

Thermal restriction matrix

Table 41. Processor and heat sink matrix

Heat sink	Processor TDP
STD HSK	≤ 185 W
L-type HSK	≥ 195 W

Table 42. Label reference

Label	Description
STD	Standard fan
HSK	Heat sink

Table 42. Label reference (continued)

Label	Description
LP	Low Profile
FH	Full Height
DLC	Direct Liquid Cooling

i NOTE: The essential component in the configuration determines the ambient temperature of the configuration. For example, if the processor supported ambient temperature is 35°C (95°F), the DIMM is 35°C (95°F), and the GPU is 30°C (86°F), the combined configuration can only support 30°C (86°F).

Table 43. Thermal restriction matrix for air cooled configurations

Configuration			32 x 2.5-inch SAS	16 x 2.5-inch SAS + 8 x 2.5-inch NVMe	24 x 2.5-inch NVMe	16 x 2.5-inch SAS	16 x EDSFF E3.S NVMe	8 x 2.5-inch SAS + 16 x EDSFF E3.S NVMe	8 x 2.5-inch SAS
Rear storage			No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives
CPU SKUs	TDP	T-Case max center (°C)	Ambient temperature						
6416H	165 W	82	45°C (113°F)	35°C (95°F)	35°C (95°F)	45°C (113°F)	35°C (95°F)	35°C (95°F)	45°C (113°F)
6418H	185 W	81	45°C (113°F)	35°C (95°F)	35°C (95°F)	45°C (113°F)	35°C (95°F)	35°C (95°F)	45°C (113°F)
6434H	195 W	64	45°C (113°F)	35°C (95°F)	35°C (95°F)	45°C (113°F)	35°C (95°F)	35°C (95°F)	45°C (113°F)
6448H	250 W	83	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)
8450H ¹	250 W	76	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)
8444H ¹	270 W	72	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)
8454H ¹	270 W	71	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)
8460H ¹	330 W	76	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)
8468H ¹	330 W	77	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)
8490H ¹	350 W	79	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)
Memory			Ambient temperature						
256 GB RDIMM			35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)
128 GB RDIMM			35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)

Table 43. Thermal restriction matrix for air cooled configurations (continued)

Configuration	32 x 2.5-inch SAS	16 x 2.5-inch SAS + 8 x 2.5-inch NVMe	24 x 2.5-inch NVMe	16 x 2.5-inch SAS	16 x EDSFF E3.S NVMe	8 x 2.5-inch SAS + 16 x EDSFF E3.S NVMe	8 x 2.5-inch SAS
Rear storage	No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives
96 GB RDIMM ¹	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)
64 GB RDIMM	N/A*	N/A*	N/A*	N/A*	N/A*	N/A*	N/A*
32 GB RDIMM	N/A*	N/A*	N/A*	N/A*	N/A*	N/A*	N/A*
16 GB RDIMM	N/A*	N/A*	N/A*	N/A*	N/A*	N/A*	N/A*
GPU	Ambient temperature						
Double width (300 W)	N/A	N/A	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)

- NOTE:** *Memory has the same thermal restrictions of the processor used.
- NOTE:** Up to six standard (STD) dual fan modules must be installed in all the configurations.
- NOTE:** GPU air shroud is required when GPUs are installed in the system.
- NOTE:** DIMM blanks must be installed in empty DIMM slots.
- NOTE:** ¹Only the processors that are listed above can support 96 GB RDIMM.
- NOTE:** When riser slots four and nine are used in processors 6416H, 6418H, 6434H, 6448H, 8450H, 8444H, and 8454H, the supported ambient temperature is 35°C.

Table 44. Thermal restriction matrix for Direct Liquid Cooled configurations

Configuration			32 x 2.5-inch SAS	16 x 2.5-inch SAS + 8 x 2.5-inch NVMe	24 x 2.5-inch NVMe	16 x 2.5-inch SAS	16 x EDSFF E3.S NVMe	8 x 2.5-inch SAS + 16 x EDSFF E3.S NVMe	8 x 2.5-inch SAS
Rear storage			No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives
CPU SKUs	TDP	T-Case max center (°C)	Ambient temperature						
6416H	165 W	82	45°C (113°F)	35°C (95°F)	35°C (95°F)	45°C (113°F)	35°C (95°F)	35°C (95°F)	45°C (113°F)
6418H	185 W	81	45°C (113°F)	35°C (95°F)	35°C (95°F)	45°C (113°F)	35°C (95°F)	35°C (95°F)	45°C (113°F)
6434H	195 W	64	45°C (113°F)	35°C (95°F)	35°C (95°F)	45°C (113°F)	35°C (95°F)	35°C (95°F)	45°C (113°F)
6448H	250 W	83	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)

Table 44. Thermal restriction matrix for Direct Liquid Cooled configurations (continued)

Configuration			32 x 2.5-inch SAS	16 x 2.5-inch SAS + 8 x 2.5-inch NVMe	24 x 2.5-inch NVMe	16 x 2.5-inch SAS	16 x EDSFF E3.S NVMe	8 x 2.5-inch SAS + 16 x EDSFF E3.S NVMe	8 x 2.5-inch SAS
Rear storage			No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives	No Rear Drives
8450H ¹	250 W	76	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)
8444H ¹	270 W	72	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)
8454H ¹	270 W	71	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)
8460H ¹	330 W	76	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)
8468H ¹	330 W	77	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)
8490H ¹	350 W	79	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)
Memory			Ambient temperature						
256 GB RDIMM			35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)
128 GB RDIMM			35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)
96 GB RDIMM ¹			40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)	35°C (95°F)	35°C (95°F)	40°C (104°F)
64 GB RDIMM			N/A*	N/A*	N/A*	N/A*	N/A*	N/A*	N/A*
32 GB RDIMM			N/A*	N/A*	N/A*	N/A*	N/A*	N/A*	N/A*
16 GB RDIMM			N/A*	N/A*	N/A*	N/A*	N/A*	N/A*	N/A*
GPU			Ambient temperature						
Double width (300 W)			N/A	N/A	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)	35°C (95°F)

NOTE: *Memory has the same thermal restrictions of the processor used.

NOTE: Up to six standard (STD) dual fan modules must be installed in all the configurations.

NOTE: DIMM blanks must be installed in empty DIMM slots.

NOTE: ¹Only the processors that are listed above can support 96 GB RDIMM.

Thermal air restrictions

Table 45. Air cooling configurations thermal restriction for AHSRAE A3 and A4

ASHRAE	A3/40°C (104°F)	A4/45°C (113°F)
Processor	Processors with a TDP greater than or equal to 330 W are not supported.	Processors with a TDP greater than or equal to 250 W are not supported.
PSU	Four PSUs are required in redundant mode. If there is a PSU failure, system performance may be reduced.	
PCIe card	Non-Dell qualified peripheral cards and peripheral cards greater than 25 W are not supported.	
GPU/FPGA	Not supported	
DIMM	128 GB, or greater capacity DIMMs are not supported.	
NVMe storage	2.5-inch NVMe storage is not supported.	
OCP	Supported with 85°C (185°F) active optic cable and cards tier >5 are not supported.	
BOSS	BOSS-N1 is not supported.	
PCIe slot	Slot numbers four and nine are not supported.	

Table 46. Liquid cooling configurations thermal restriction for AHSRAE A3 and A4

ASHRAE	A3/40°C (104°F)	A4/45°C (113°F)
PSU	Four PSUs are required in redundant mode. If there is a PSU failure, system performance may be reduced.	
PCIe card	Non-Dell qualified peripheral cards and peripheral cards greater than 25 W are not supported.	
GPU/FPGA	Not supported	
DIMM	128 GB, or greater capacity DIMMs are not supported.	
NVMe storage	2.5-inch NVMe storage is not supported.	
OCP	Supported with 85°C (185°F) active optic cable and cards tier >5 are not supported.	Supported with 85°C (185°F) active optic cable and cards tier >4 are not supported.
BOSS	BOSS-N1 is not supported.	

Appendix B. Standards compliance

The system conforms to the following industry standards.

Table 47. Industry standard documents

Standard	URL for information and specifications
ACPI Advance Configuration and Power Interface Specification, v6.4	ACPI
Ethernet IEEE Std 802.3-2022	IEEE Standards
MSFT WHQL Microsoft Windows Hardware Quality Labs	Windows Hardware Compatibility Program
IPMI Intelligent Platform Management Interface, v2.0	IPMI
DDR5 Memory DDR5 SDRAM Specification	JEDEC Standards
PCI Express PCI Express Base Specification, v5.0	PCIe Specifications
PMBus Power System Management Protocol Specification, v1.2	Power System Management Protocol Specification
SAS Serial Attached SCSI, 3 (SAS-3) (T10/INCITS 519)	SCSI Storage Interfaces
SATA Serial ATA Rev. 3.3	SATA IO
SMBIOS System Management BIOS Reference Specification, v3.3.0	DMTF SMBIOS
TPM Trusted Platform Module Specification, v1.2 and v2.0	TPM Specifications
UEFI Unified Extensible Firmware Interface Specification, v2.7	UEFI Specifications
PI Platform Initialization Specification, v1.7	
USB Universal Serial Bus v2.0 and SuperSpeed v3.0 (USB 3.1 Gen1)	USB Implementers Forum, Inc. USB
NVMe Express Base Specification. Revision 2.0c	NVMe
NVMe Command Set Specifications	
1. NVM Express NVM Command Set Specification. Revision 1.1c	
2. NVM Express Zoned Namespaces Command Set. Revision 1.0c	
3. NVM Express® Key Value Command Set. Revision 1.0c	
NVMe Transport Specifications	
1. NVM Express over PCIe Transport. Revision 1.0c	
2. NVM Express RDMA Transport Revision. 1.0b	
3. NVM Express TCP Transport. Revision 1.0c	
NVMe NVM Express Management Interface. Revision 1.2c	
NVMe NVMe Boot Specification. Revision 1.0	

Appendix C Additional resources

Table 48. Additional resources

Resource	Description of contents	Location
Installation and Service Manual	<p>This manual, available in PDF format, provides the following information:</p> <ul style="list-style-type: none"> • Chassis features • System Setup program • System indicator codes • System BIOS • Remove and replace procedures • Diagnostics • Jumpers and connectors 	Support Manuals
Getting Started Guide	<p>This guide ships with the system, and is also available in PDF format. This guide provides the following information:</p> <ul style="list-style-type: none"> • Initial setup steps 	Support Manuals
Rack Installation Guide	This document ships with the rack kits, and provides instructions for installing a server in a rack.	Support Manuals
System Information Label	The system information label documents the system board layout and system jumper settings. Text is minimized due to space limitations and translation considerations. The label size is standardized across platforms.	Inside the system chassis cover
QR code for system resources	This code on the chassis can be scanned by a phone application to access additional information and resources for the server, including videos, reference materials, service tag information, and Dell contact information.	Inside the system chassis cover
Enterprise Infrastructure Planning Tool (EIPT)	The Dell online EIPT enables easier and more meaningful estimates to help you determine the most efficient configuration possible. Use EIPT to calculate the power consumption of your hardware, power infrastructure, and storage.	calc

Appendix D: Services

Topics:

- [Default service levels](#)
- [ProDeploy Infrastructure Suite](#)
- [Supplemental Deployment Services](#)
- [Unique Deployment Scenarios](#)
- [DAY 2 - Automation Services with Ansible](#)
- [ProSupport Infrastructure Suite](#)
- [Specialty Support Services](#)
- [Dell Technologies Consulting Services](#)
- [Resources](#)

Default service levels

Dell sales tools like DSA, OSC, Guided Journey, DellStar, and others are defaulted with standard configurations to make quoting easier. The system defaults for services for all T-Series platforms are listed below:

1. **Support default:** 3 years, ProSupport Next BusinessDay (NBD) Onsite service which includes comprehensive 24x7 predictive and reactive support for hardware and software.
2. **Deployment default:** The R960 is defaulted to ProDeploy which provides remote software configuration and choice of hardware installation (onsite or guided).

ProDeploy Infrastructure Suite

ProDeploy Infrastructure Suite provides various deployment offerings that satisfy a customer's unique needs. It is made up of five offers: ProDeploy Configuration Services, ProDeploy Rack Integration Services, Basic Deployment, ProDeploy, and ProDeploy Plus.

ProDeploy Infrastructure Suite

Versatile choices for accelerated deployments

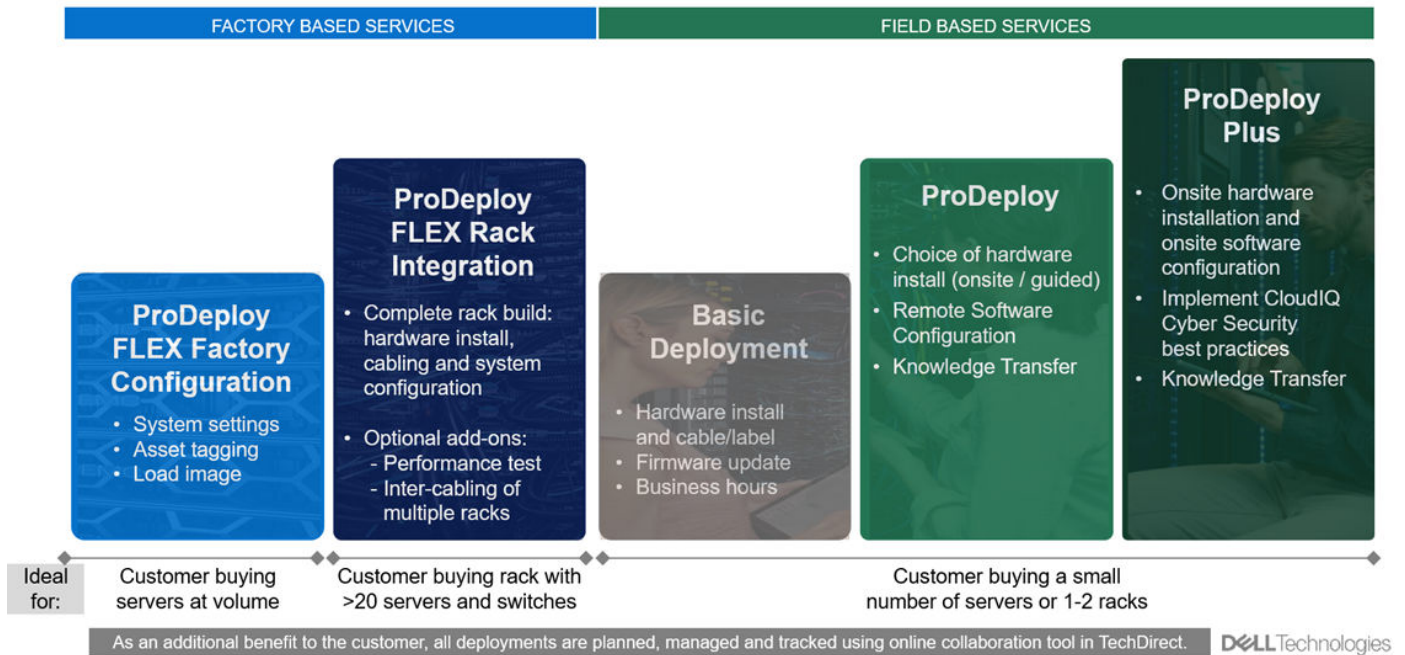


Figure 41. ProDeploy Infrastructure Suite

Factory-based Services

The new Factory Services consist of two tiers of deployment that happen prior to shipping to the Customer's site.

ProDeploy FLEX Factory Configuration

Ideal for Customers buying servers in volume and seeking pre-configuration prior to shipping such as: custom image, system settings, and asset tagging so it arrives ready to use out of the box. Furthermore, servers are packaged and bundled to meet specific shipping and distribution requirements for each customer location to facilitate the rollout process. Once the server is onsite, Dell can install and configure the server to the environment using any of the field-based deployment services outlined in the next section.

ProDeploy FLEX Rack Integration

Ideal for customers seeking to build out fully integrated racks prior to shipping. These rack builds include hardware install, cabling, and full system configuration. You can also add-on a factory stress test and an optional on-site final rack configuration to complete the rack installation.

- STANDARD SKUs for Rack Integration is available in the USA only and requires:
 - 20 or more devices (R and C series servers, VxRail, and all Dell or non-Dell switches).
 - Shipping to contiguous USA.
- USE CUSTOM QUOTE for Rack Integration scenarios that require:
 - Shipment to any country or region outside USA or shipping outside contiguous USA
 - Shipping to multiple locations
 - Racks containing fewer than 20 servers
 - Any rack that includes Storage.

ProDeploy Flex | Modular deployment (built in factory, onsite or remote)

Pre -deployment	Single point of contact for project management	●
	Expanded end-to-end project management	Selectable
	Site readiness review and implementation planning	●
Deployment	Deployment service hours	24/7
	Hardware installation options ¹	Onsite, factory ^{2,5} or remote ³
	System software installation and configuration options ¹	Onsite, factory ^{2,5} or remote ³
	Multivendor networking deployment ⁴	Onsite, factory ^{2,5} or remote ³
	Onsite Deployment in remote locations	Selectable
	Onsite Deployment in challenging environments	Selectable
	Onsite Deployment with special site-based protocols or requirements	Selectable
	Install connectivity software based on Secure Connect Gateway technology	●
	Dell NativeEdge Orchestrator deployment	Selectable
	Configure 3 rd party software applications and workloads ⁴	Selectable
Post -deployment	Deployment verification, documentation, and knowledge transfer	●
	Configuration data transfer to Dell support	●
Online collaboration	Online collaborative environment - Planning, managing and tracking delivery process	●

¹ Hardware and Software delivery methods can be independently chosen; selecting Rack integration for software requires hardware Rack integration to also be selected.

² Factory Rack Integration for server and VxRail; includes associated Dell network switches; final onsite rack installation available.

³ Remote hardware option includes project specific instructions, documentation and live expert guidance for hardware installation.

⁴ Select 3rd party multivendor networking and software applications.

⁵ Pair with Field Onsite Hardware service for final installation.

Figure 42. ProDeploy Flex modular services

Field-based services

● ProDeploy Plus:

Elevate Infrastructure deployments with our most complete service from planning through onsite hardware installation and software configuration including the implementation of cybersecurity best practices. ProDeploy Plus provides the skill and scale that is needed to successfully perform demanding deployments in today's complex IT environments. The deployment starts with a site readiness review and implementation plan. Certified deployment experts perform the software configuration to include setup of leading operating systems and hypervisors. Dell will also configure PowerEdge software tools to include iDRAC and OpenManage system utilities and support AIOps platforms: MyService360, TechDirect, and CloudIQ. Unique to ProDeploy Plus, the cybersecurity implementation helps customers understand potential security risks and make recommendations for reducing product attack surfaces. The system is tested, validated prior to completion. The customer will also receive full project documentation and knowledge transfer to complete the process.

● ProDeploy:

ProDeploy provides remote software configuration and choice of hardware installation (onsite or guided). ProDeploy is great for customers who are price sensitive or willing to participate in some portion of the deployment to include providing remote access to their network. The ProDeploy remote software implementation includes everything that is mentioned in ProDeploy Plus except it does not include the added value, cybersecurity implementation and best practices.

ProDeploy Infrastructure Suite | Field services

		Basic Deployment	ProDeploy	ProDeploy Plus
Pre-deployment	Single point of contact for project management	-	●	In region
	Site readiness review and implementation planning	-	●	●
Deployment	Deployment service hours	Business hours	24/7	24/7
	Hardware installation options	Onsite	Onsite or guided ¹	Onsite
	System software installation and configuration options	-	Remote	Onsite
	Install connectivity software based on Secure Connect Gateway technology ²	-	●	●
	Implement CyberSecurity best practices and policies in APEX AIOps Infrastructure Observability	-	-	●
Post-deployment	Deployment verification, documentation and knowledge transfer	-	●	●
	Configuration data transfer to Dell technical support	-	●	●
Online collaboration	Online collaborative platform in TechDirect for planning, managing and tracking delivery	-	●	●

¹ Choose from onsite hardware installation or a guided option including project specific instructions, documentation and live expert guidance

² Post deployment use for intelligent, automated support & insights

Figure 43. ProDeploy Infrastructure Suite - Field services

Supplemental Deployment Services

Additional ways to expand scope or deploy for unique scenarios.

Two Host Adder (requires PD/PDP)

Deploying new storage, compute, or networking devices may require interconnection to other servers (also called hosts). The Dell delivery team will set up four hosts per device as part of every ProDeploy service. For example, if the customer is buying two storage arrays the ProDeploy service will automatically include connectivity of four hosts each (4x2=8 total hosts per project since there are two devices). This supplemental "Two Host Adder" service provides for the configuration of additional hosts above what is already provided as part of the ProDeploy service. In many cases, customers can work with us while we set up the included hosts, so they may understand how to do the rest themselves. Always ask the customer how many hosts are being connected and sell the host adder depending on the customer's technology skillset. Note that this service applies to the connectivity of Dell devices not 3rd party devices.

Additional Deployment Services (ADT) - sold with or without PD/PDP

You can expand the scope of a ProDeploy engagement leveraging Additional Deployment Time (ADT). ADT covers additional tasks above the normal deliverables of the ProDeploy offers. ADT can also be used as a standalone service without ProDeploy. SKUs are available for both Project Management and Technical Resource Expertise. SKUs are sold as blocks of four hours remote or eight hours onsite. The delivery team can assist in scoping the number of hours required for additional tasks.

Data Migration Services

Migrating data sets is no easy task. Our experts use proven tools and processes to streamline data migrations and avoid compromising data. A customer project manager works with our experienced team of experts to create a migration plan. Data migration is part of every technology upgrade, platform change, and shift to the cloud. You can rely on Dell data migration services to perform a seamless transition.

Residency Services

Certified technical professionals act like an extension of your IT staff to enhance internal capabilities and resources and help you realize faster adoption and maximized ROI of new technology. Residency Services help customers transition to new capabilities quickly by leveraging specific technology skill sets. Residency experts can provide post implementation management and knowledge transfer that is related to a new technology acquisition or day-to-day operational management of the IT infrastructure.

- Global experts available to serve in-person (onsite) or virtual (remote)
- Engagements starting at 2 weeks with flexibility to adjust

Unique Deployment Scenarios

Custom Deployment Services

When a deployment is beyond the scope of the ProDeploy Infrastructure Suite, you can turn to the custom deployment services team to address complex implementation scenarios and unique customer requirements. The Dell custom deployment team is staffed with solution architects who assist with customer scoping calls to define the project and develop the statement of work. Custom services can handle a wide range of deployments that can be performed in the factory or onsite. All custom engagement services are requested through SFDC.

ProDeploy FLEX

ProDeploy Flex is a new service and a powerful tool for you to attach more services and improve revenue and margins. The ProDeploy Flex modular offer allows sales teams to build and better tailor services by mixing factory and field delivery options. You can also select special deployment scenarios without going to the custom order desk. FLEX is ideal for unique deployments where ProDeploy or ProDeploy Plus are not an adequate answer to the customer needs.

Key features of ProDeploy FLEX

- Build deployment quotes using modular, selectable features for both hardware and software.
- The system automatically scales pricing based on volume.
- Ideal for customers who require NativeEdge Orchestrator or edge deployments
- Ability to add deployment services to third-party networking devices

Deployment of HPC

High-Performance Computing (HPC) implementations require specialists that understand advanced feature sets. Dell deploys the world's fastest systems and understands the nuances that make them perform. HPC deployments are most often scoped as custom service engagements, however we can do smaller HPC clusters under 300 nodes using a standard ProDeploy SKU. Any standard SKU for HPC deployment will be sold as one base SKU per cluster (ProDeploy for HPC Base) along with one ProDeploy for HPC Add-on for each device in the cluster (server nodes and switches).

- Scope of ProDeploy for HPC: *Available as standard SKUs in the US and Canada. Custom Service would be required for all other regions.

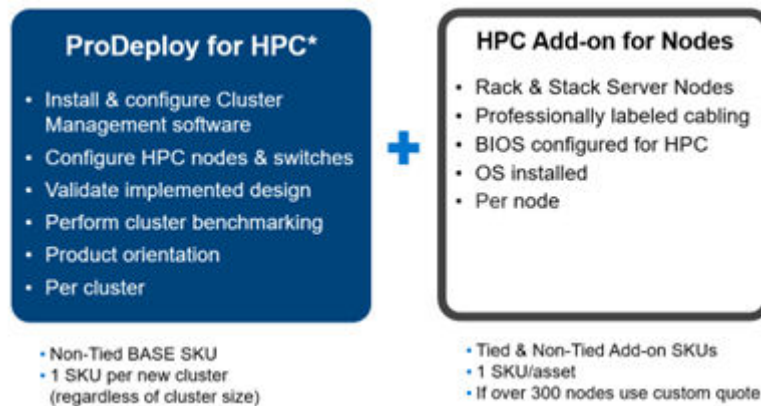


Figure 44. Standard deliverables of ProDeploy for HPC

Build HPC solutions for your unique requirements
 Choose ProDeploy for HPC or Custom deploy
 ProDeploy service includes configuration of most OS, cluster mgmt., networking and benchmarking



Figure 45. Visual view of HPC deployment options to include hardware and software

DAY 2 - Automation Services with Ansible

Dell solutions are built as "automation ready" with integrated APIs (Application Programming Interfaces) to allow customers to programmatically call actions on the product through code. Although Dell has published Ansible automation use cases, some customers need additional assistance with GitOps. By the end of the service, the customer will have the foundational components required to accelerate automation and understand how the programming works together: Day 1 and Day 2 use case automation scripts (ansible modules), CI/CD tool (Jenkins), and Version control (Git).

ProSupport Infrastructure Suite

ProSupport Infrastructure Suite is a set of support services that enable customers to build the solution that is right for their organization. It is an industry-leading, enterprise-class support that aligns with the criticality of your systems, the complexity of your environment, and the allocation of your IT resources.

ProSupport Infrastructure Suite | Enhanced value across all offers!

	Basic Hardware Support	ProSupport for Infrastructure	ProSupport Plus for Infrastructure	Changes with August 2023 release
Technical support availability and response objective	9/5, immediate	24/7, immediate	24/7, immediate	No change
Covered products	Hardware	Hardware & Software	Hardware & Software	No change
Onsite response service level	NBD	NBD or 4-hour	4-hour	ProSupport Plus NBD is retired
ProSupport AIOps platforms	•	•	•	MyService360 and TechDirect (all offers) CloudIQ (ProSupport & ProSupport Plus)
Dell Security Advisories	•	•	•	Available on additional products
Proactive issue detection with automated case creation	•	•	•	New to Basic
Predictive hardware anomaly detection		•	•	New to ProSupport
Access to software updates		•	•	No change
CloudIQ health and cybersecurity monitoring & analytics		•	•	Enhanced features
Incident Manager for Severity 1 cases		•	•	No change
Mission Critical support			•	Enhanced features
Priority access to remote senior support engineers ¹			•	No change
Service Account Manager			•	No change
Proactive system maintenance			•	No change
Limited 3 rd party software support ²			•	No change

¹Based on availability

²Software license can be purchased through Dell or BYOL - see Service Descriptions for details.

Dell Technologies

Figure 46. ProSupport Enterprise Suite

ProSupport Plus for Infrastructure

ProSupport Plus for Infrastructure is the ultimate solution for customers seeking preventative maintenance and optimal performance on their business-critical assets. The service caters to customers who require proactive, predictive, and personalized support for systems that manage critical business applications and workloads. When customers purchase PowerEdge server, we recommend ProSupport Plus, our proactive and preventative support service for business-critical systems. ProSupport Plus provides all the benefits of ProSupport, including the following "Top five reasons to buy PSP".

1. Priority access to specialized support experts - immediate, advanced troubleshooting from an engineer that understands Dell infrastructure solutions.
2. Mission Critical Support – when critical (Severity 1) support issues happen, the customer is assured that we will do all we can to get them back up and running as quickly as possible.
3. Service Account Manager – a customer's #1 support advocate, ensuring they get the best possible proactive and predictive support experience.
4. Systems maintenance – on a semi-annual basis, we will keep a customer's ProSupport Plus system(s) up to date by installing the latest firmware, BIOS, and driver updates to improve performance and availability.
5. 3rd party software support – Dell is a customer's single point of accountability for any eligible 3rd party software installed on their ProSupport Plus system, whether they purchased the software from us or not.

ProSupport for Infrastructure

Comprehensive 24x7 support for hardware and software - best for production, but not critical, workloads and applications. The ProSupport service offers highly trained experts around the clock and around the globe to address IT needs. We help minimize disruptions and maximize availability of PowerEdge server workloads with:

- 24x7 support through phone, chat and online
- A central point of accountability for all hardware and software issues
- Hypervisor, operating system and application support
- Dell security advisories
- Onsite response service levels 4 hour or Next Business Day options
- Proactive issue detection with automated case creation
- Predictive hardware anomaly detection

- Incident Manager assigned for Severity 1 cases
- Collaborative third-party support
- Access to AIOps Platforms - (MyService360, TechDirect, and CloudIQ)
- Consistent experience regardless of where customers are located or what language they speak.

Basic Hardware Support

Provides reactive hardware support during normal business hours, excluding local national holidays. No software support or software related guidance. For improved levels of support choose ProSupport or ProSupport Plus.

Specialty Support Services

Optional specialty support services complement the ProSupport Infrastructure Suite to provide additional proficiencies that are critical for modern data center operations.

Hardware coverage add-ons to ProSupport

- **Keep Your Hard Drive (KYHD) and Keep Your Component (KYC):** Normally if a device fails under warranty, Dell replaces it using a one-for-one exchange process. KYHD / KYC gives you the option to retain your device. It provides full control of sensitive data and minimizes security risk by letting you retain possession of failed drives / components when receiving replacement parts without incurring additional cost.
- **Onsite Diagnosis Service:** Ideal for sites with non-technical staff. Dell field technician performs initial troubleshooting diagnosis onsite and transfers to Dell remote engineers to resolve the issue.
- **ProSupport Add-on for HPC:** Sold as an add-on to a ProSupport service contract, the ProSupport Add-on for HPC provides solution-aware support to cover the additional requirements that are required to maintain an HPC environment such as:
 - Access to senior HPC experts
 - Advanced HPC cluster assistance: performance, interoperability, and configuration
 - Enhanced HPC solution level end-to-end support
 - Remote pre-support engagement with HPC Specialists during ProDeploy implementation
- **ProSupport Add-on for Telco (Respond & Restore):** An add-on service designed for the top 31 TELCO customers globally, Respond & Restore provides direct access to Dell solution experts who specialize in TELCO carrier-grade support. This add-on also provides a hardware uptime guarantee, meaning if a system fails, Dell will have it installed and operational within 4 hours for Severity 1 issues. Dell incurs penalties and fees if SLAs are not met.

Supplemental Site-wide Expertise

- **Multivendor Support Service:** Support your 3rd party devices as one service plan for servers, storage and networking (includes coverage for: Broadcom, Cisco, Fujitsu, HPE, Hitachi, Huawei, IBM, Lenovo, NetApp, Oracle, Quanta, SuperMicro & others).
- **Technical Account Manager:** Designated technology lead who monitors and manages performance and configuration of specific technology sets.
- **Designated Remote Support:** Personalized support expert who manages all troubleshooting and resolution of IT assets

Services for large enterprises

- **ProSupport One for Data Center:** ProSupport One for Data Center offers flexible site-wide support for large and distributed data centers with more than 1,000 assets (combined total of server, storage, networking, etc.). This offering is built on standard ProSupport features that leverage our global scale and are tailored to specific customer needs. While not for everyone, this service option offers a truly unique solution for our largest customers with the most complex environments.
 - Team of assigned Services Account Managers with remote or onsite options
 - Assigned technical and field engineers who are trained on the customer's environment and configurations
 - On-demand reporting and recommendations enabled by ProSupport AIOps tools (MyService360, TechDirect & CloudIQ)
 - Flexible onsite support and parts options that fit their operational model

- A tailored support plan and training for their operations staff
- **Logistics Online Inventory Solution (LOIS):** Ideal for large organizations that have their own staff to support their data center. Dell offers a service called Logistics Online Inventory Solution which is an onsite parts locker that provides self-maintainers with a local inventory of common replacement components. Having access to these parts lockers allows the self-maintainer to replace a failed component immediately without delay. Each replacement part would automatically initiate a replenishment of the parts inventory that is shipped next day or delivered onsite by Dell during a regular scheduled visit (called Scheduled Onsite Service). As part of the LOIS system, customers can integrate their systems directly to Dell TechDirect using APIs to help streamline the support management process.

End-of-Life Services

- **Post Standard Support (PSS):** Extend service life beyond the initial seven years of ProSupport, adding up to five more additional years of hardware coverage
- **Data Sanitization & Data Destruction:** Renders data unrecoverable on repurposed or retired products, ensuring security of sensitive data and enabling compliance and provides NIST compliant certification.
- **Asset Recovery Services:**Recycle, resale, and disposal of hardware. Helps you securely and responsibly retire IT assets that are no longer needed while protecting both your business and the planet.

Dell Technologies Consulting Services

Our expert consultants help customers transform faster, and quickly achieve business outcomes for the high-value workloads Dell PowerEdge systems can handle. From strategy to full-scale implementation, Dell Technologies Consulting can help you determine how to perform IT, workforce, or application transformation. We use prescriptive approaches and proven methodologies that are combined with the portfolio and partner ecosystem of Dell Technologies to help achieve real business outcomes. From multicloud, applications, DevOps, and infrastructure transformations, to business resiliency, data center modernization, analytics, workforce collaboration, and user experiences-we are here to help.

Dell Managed Services

Some customers prefer Dell to manage the complexity and risk of daily IT operations, Dell-Managed Services uses proactive, AI enabled delivery operations and modern automation to help customers realize desired business outcomes from their infrastructure investments. With these technologies, our experts run, update, and fine-tune customer environments that are aligned with service levels, while providing environment-wide and down-to-the-device visibility. There are two types of managed service offers. First the outsourcing model or CAPEX model where Dell manages the customer-owned assets using our people and tools. The second is the as-a-Service model or OPEX model called APEX. In this service, Dell owns all technology and all the management of it. Many customers will have a blend of the two management types depending on the goals of the organization.

Managed	Outsourcing or CAPEX model	APEX	as-a-Service or OPEX model
<p>We manage your technology using our people and tools.¹</p> <ul style="list-style-type: none"> • Managed detection and response* • Technology Infrastructure • End-user (PC/desktop) • Service desk operations • Cloud Managed (Pub/Private) • Office365 or Microsoft Endpoint 		<p>We own all technology so you can off-load all IT decisions.</p> <ul style="list-style-type: none"> • APEX Cloud Services • APEX Flex on Demand elastic capacity • APEX Data Center Utility pay-per-use model 	

1 – Some minimum device counts may apply. Order via: ClientManagedServices.sales@dell.com

* Managed detection and response covers the security monitoring of laptops, servers, & virtual servers. Min. 50 devices combined. No Networking or Storage-only systems [SAN/NAS]. Available in 32 countries. [Details here](#)

Figure 47. Dell Managed Services

Managed Detection and Response (MDR)

Dell Technologies Managed Detection and Response (MDR) is powered by Secureworks Taegis XDR software platform. MDR is a managed service that secures the customer's IT environment against malicious actors and provides remediation if and when a threat is identified. When a customer purchases MDR, they receive the following features from our team:

- Dell badge resources
- Agent rollout assistance to help deploy the Secureworks Endpoint Agent
- 24x7 threat detection & investigation
- Up to 40 hrs per quarter of response and active remediation activities
- If the customer experiences a breach, we will provide up to 40 hrs per year of Cyber incident response initiation
- Quarterly reviews with the customer to review the data

Dell Technologies Education Services

Build the IT skills required to influence the transformational outcomes of the business. Enable talent and empower teams with the right skills to lead and perform transformational strategy that drives competitive advantage. Leverage the training and certification that is required for real transformation.

Dell Technologies Education Services offers PowerEdge server training and certifications that are designed to help customers achieve more from their hardware investment. The curriculum delivers the information and the practical, firsthand skills that their team must confidently install, configure, manage, and troubleshoot Dell servers.

To learn more or register for a class today, see Education.Dell.com.

Resources

Services Central: [Services for PowerEdge](#)

Sales Portal: [Services for Server Knowledge Center](#)